

SAMSUNG SSD SZ1735

Specification (PCIe® NVMe™ 2.5")

Datasheet

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| Part Number | Capacity ¹⁾ | LBA (512 Bytes size) |
|---------------------|------------------------|----------------------|
| MZWJ800HMGQ - 00007 | 800GB | 1,562,824,368 |
| MZWJ1T6HMGG - 00007 | 1.6TB | 3,125,627,567 |
| MZWJ3T2HMHN - 00007 | 3.2TB | 6,251,233,967 |

NAND

- Z-NAND Flash Memory

FEATURES

- PCI Express Gen3
 - Single port x4 lanes
 - Dual port x2 lanes
- Enhanced Power-Loss Data Protection
- LDPC ECC
- End-to-End Data Protection
- Support Hot Plug/Removal
- Support up to 128 I/O Queues per Port
- Support Deallocate (a.k.a. TRIM) Command
- Support PCI Express AER (Advanced Error Reporting)
- Support 129 vectors for MSI-X
- Support SSD Enhanced S.M.A.R.T. Feature Set
- Hardware based AES-XTS 256-bit Encryption Engine
- Static and Dynamic Wear Leveling
- Support UEFI Expansion ROM
- Support SFF-8639 SMBus

DRIVE CONFIGURATION

- Form Factor SFF-8639 2.5-inch
- Interface PCI Express Gen3 x4
- Bytes per Sector 512, 520, 4096, 4160 Bytes

PERFORMANCE SPECIFICATIONS²⁾

- Data Transfer Rate² (128KB data size)
 - Sequential Read³ Up to 3,200 MB/s
 - Sequential Write³ Up to 3,200 MB/s
- Data I/O Speed² (4KB data size, Sustained)
 - Random Read Up to 800K IOPS
 - Random Write Up to 250K IOPS
- Latency (Sustained random workload)
 - Read (typical)⁴ 20 us
 - Read (best)⁴ 12 us
 - Write (typical)⁵ 20 us
 - Drive Ready Time (typical) 2 sec
- Quality of service
 - Read/Write (99%) 20/20 us
- Performance Consistency
 - Read/Write (99.9%) Up to 98/95%

COMPLIANCE

- PCI Express Base Specification Rev. 3.0
- NVM Express Specification Rev. 1.2
- Enterprise SSD Form Factor Ver. 1.0a

CERTIFICATIONS AND DEDARATIONS

- c-UL-us, TUV-GS, CB, CE, BSMI, KC, Morocco, VCCI, RCM, FCC, IC

PRODUCT ECOLOGICAL COMPLIANCE

- RoHS

RELIABILITY SPECIFICATIONS

- Uncorrectable Bit Error Rate 1 sector per 10¹⁷ bits read
- MTBF 2,000,000 hours
- Power on Cycles (Ambient) 20,000
- Component Design Life 5 years
- Endurance 30 DWPD
- TBW (@4KB Random Write)
 - 800GB 43.8 PB
 - 1.6TB 87.6 PB
 - 3.2TB 175.2 PB
- Data Retention 3 months

ENVIRONMENTAL SPECIFICATIONS

- Temperature, Ambient (Ta⁶⁾
 - Operating 0 ~ 55 °C
 - Non-operating -40 ~ 85 °C
- Humidity (Non-operating) 5 ~ 95%
- Shock 1,500 G / 0.5msec
- Vibration
 - Sweep Sinusoidal 20 Gpeak, 10 ~ 2000Hz

POWER REQUIREMENTS

- Supply Voltage / Tolerance 12V±10%
- Active⁷ (max. RMS) 12 W
- Idle (typ.) 6 W

PHYSICAL DIMENSION

- Width 69.85 ± 0.25 mm
- Length 100.20 ± 0.25 mm
- Height 14.80 ± 0.20 mm
- Weight Up to 190 g

OPERATING SYSTEMS

Windows Server 2008 R2 64-bit
 Windows Server 2012 64-bit
 Windows Server 2012 R2 64-bit
 RHEL 6.4 (Kernel 2.6.32)
 RHEL 6.5 (Kernel 2.6.32)
 RHEL 6.6 (Kernel 2.6.32)
 RHEL 7 (Kernel 3.10.0)
 RHEL 7.1 (Kernel 3.10.0)
 SLES 11 SP3 (Kernel 3.0.13)
 SLES 12 (Kernel 3.12.28)

NOTE: Specifications are subject to change without notice.

1) 1MB = 1,000,000 Bytes, 1GB = 1,000,000,000 Bytes, unformatted Capacity. User accessible capacity may vary depending on operating environment and formatting.

2) Based on PCI Express Gen3 x4, Random performance measured using FIO in CentOS 7.0 with queue depth 32 by 16 workers and Sequential performance with queue depth 32 by 16 worker. Actual performance may vary depending on use conditions and environment.

3) 1 MB/sec = 1,000,000 bytes/sec was used in sequential performance.

4) The read latency is measured by using FIO in CentOS 7.0 and 4KB transfer size with queue depth 1 on a random workload of sustained state.

5) The write latency is measured by using FIO in CentOS 7.0 and 4KB transfer size with queue depth 1 on a sequential workload of sustained state.

6) Ta is the ambient temperature with enough cooling airflow condition as 150LFM or faster.

7) Active power is measured using IOMeter2006 on Win Server 2012 R2.

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1.0 INTRODUCTION

1.1 General Description

This document describes the specifications of the Samsung SSD SZ1735, which is a native-PCIe SSD for enterprise application. The Samsung SSD SZ1735 presents outstanding performance with instant responsiveness to the host system, by applying the Peripheral Component Interconnect Express (PCIe) 3.0 interface standard, as well as highly efficient Non-Volatile Memory Express (NVMe) Protocol. The Samsung SSD SZ1735 delivers wide bandwidth of 3200 MB/s for sequential read speed and 3200 MB/s for sequential write speed under up to 12W power. With the help of Toggle 2.0 NAND Flash interface, the Samsung SSD SZ1735 delivers Quality of Service(99%) of 100us for random 4KB read of 800KIOPS and 600us for random 4KB write of 250KIOPS in the sustained state. By combining the enhanced reliability Samsung NAND Flash memory silicon with NAND Flash management technologies, the Samsung SSD SZ1735 delivers the extended endurance of up to 30 Drive Writes Per Day (DWPD) for 5 years, which is suitable for enterprise applications, in a HHHL form factor lineups: 800GB, 1.6TB, 3.2TB. In addition, the Samsung SSD SZ1735 supports Hot Plug insertion and removal feature by employing the efficient circuitry for Power Loss Protection (PLP). PLP solution can guarantee that data issued by the host system are written to the storage media without any loss in the event of sudden power off or sudden power failure.

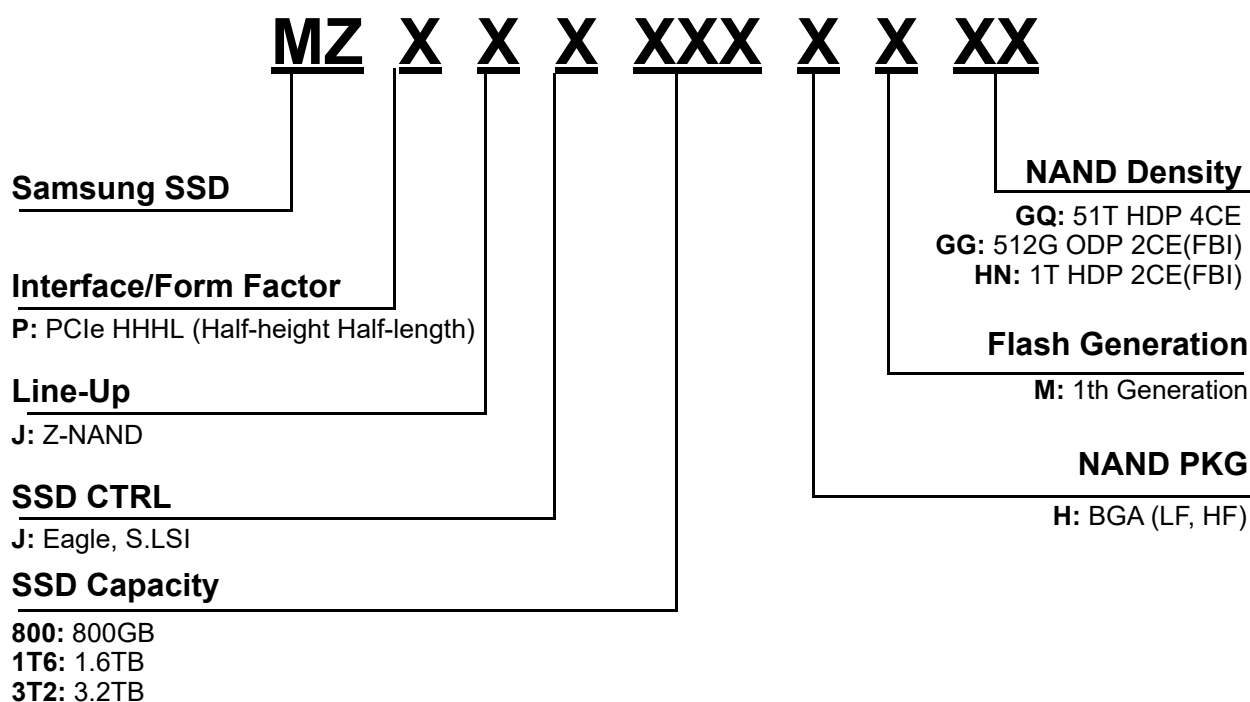
1.2 Product List

[Table 1] Product List

| Type | Capacity | Part Number |
|------------------------|----------|-------------------|
| 2.5-inch ¹⁾ | 800GB | MZWJ800HMGQ-00007 |
| 2.5-inch | 1.6TB | MZWJ1T6HMGG-00007 |
| 2.5-inch | 3.2TB | MZWJ3T2HMHN-00007 |

NOTE:
1) SFF-8639 combo (SATA, SAS, PCIe) standard connector

1.3 Ordering Information



2.0 PRODUCT SPECIFICATIONS

2.1 Capacity

[Table 2] User Capacity and Addressable Sectors

| Capacity ² | Max LBA ³ |
|-----------------------|----------------------|
| 800GB | 1,562,824,368 |
| 1.6TB | 3,125,627,567 |
| 3.2TB | 6,251,233,967 |

NOTE:
 1) Gigabyte (GB) = 1,000,000,000 Bytes, 1 Sector = 512Bytes
 2) Capacity shown in Table 2 represents the total usable capacity of the SSD which may be less than the total physical capacity. A certain area in physical capacity, not in the area shown to the user, might be used for the purpose of NAND flash management.
 3) Max. LBA shown in Table 2 represents the total user addressable sectors in LBA mode and calculated by IDEMA rule.

2.2 Performance

[Table 3] Sustained Random Read/Write Performance (IOPS)

| Maximum Performance ¹⁾ | Unit | 800GB / 1.6TB / 3.2TB |
|-----------------------------------|------|-----------------------|
| Random 4KB Read | IOPS | 800K |
| Random 4KB Write | IOPS | 250K |
| Random 8KB Read | IOPS | 400K |
| Random 8KB Write | IOPS | 100K |

NOTE:
 1) Random performance in Table 3 was measured by using FIO in CentOS7.0 with queue depth 32 by 16 workers. Measurements were performed on a full Logical Block Address (LBA) span of the drive in sustained state. Actual performance may vary depending on use conditions and environment.

[Table 4] Sequential Read/Write Performance

| Maximum Performance ¹⁾ | Unit | 800GB / 1.6TB / 3.2TB |
|--------------------------------------|------|-----------------------|
| Sequential 128KB Read ²⁾ | MB/s | 3,200 |
| Sequential 128KB Write ²⁾ | MB/s | 3,200 |

NOTE:
 1) Sequential performance in Table 4 was measured by using FIO in CentOS7.0 with queue depth 32 by 16 worker. Actual performance may vary depending on use conditions and environment.
 2) 1 MB/sec = 1,000,000 bytes/sec was used in sequential performance.

2.3 Latency

[Table 5] Latency¹ (sustained state)

| Queue Depth = 1 | Unit | 800GB / 1.6TB / 3.2TB |
|------------------------------------|------|-----------------------|
| Random Read/Write ² | us | 20 / 20 |
| Sequential Read/Write ³ | us | 20 / 20 |
| Drive Ready Time ⁴ | sec | 2 |

NOTE:
 1) Typical values.
 2) The random read/write latency is measured by using FIO in CentOS7.0 and 4KB transfer size with queue depth 1 on a random workload of sustained state.
 3) The sequential read/write latency is measured by using FIO in CentOS7.0 and 4KB transfer size with queue depth 1 on a sequential workload of sustained state.
 4) The maximum taking time to be ready for receiving commands after power-up (CSTS.Ready=1). It is expected that I/O commands may not be completed at this point.

2.4 Quality of Service (QoS)

[Table 6] Quality of Service (QoS)

| Quality of Service (99%) | Unit | 800GB | 1.6TB | 3.2TB |
|--------------------------|------|-------|-------|-------|
| Read(4KB) QD=1 | us | 20 | 20 | 20 |
| Write(4KB) QD=1 | us | 29 | 20 | 20 |
| Read(4KB) QD=32 | us | 100 | 100 | 100 |
| Write(4KB) QD=32 | us | 600 | 600 | 600 |

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| Quality of Service (99.99%) | Unit | 800GB | 1.6TB | 3.2TB |
|-----------------------------|------|-------|-------|-------|
| Read(4KB) QD=1 | us | 25 | 25 | 25 |
| Write(4KB) QD=1 | us | 23 | 23 | 23 |
| Read(4KB) QD=32 | us | 120 | 120 | 120 |
| Write(4KB) QD=32 | us | 800 | 800 | 800 |

NOTE:
 1) QoS is measured using FIO (99/99.99 %) with queue depth 1 and 32 on 4 KB random and write.
 2) QoS is measured as the maximum round-trip time taken for 99 % of commands to host.
 3) QoS is measured as the maximum round-trip time taken for 99.99 % of commands to host.

2.5 IOPS Consistency

[Table 7] IOPS Consistency

| IOPS Consistency ^{1, 2} | Unit | 800GB | 1.6TB | 3.2TB |
|----------------------------------|------|-------|-------|-------|
| Random Read (4 KB) | % | 98 | 98 | 98 |
| Random Write (4 KB) | % | 95 | 95 | 95 |
| Random Read (8 KB) | % | 98 | 98 | 98 |
| Random Write (8 KB) | % | 95 | 95 | 95 |

NOTE:
 1) IOPS consistency measured using FIO with queue depth 128.
 2) IOPS Consistency (%) = (IOPS in the 99.9% slowest 1-second interval)/(average IOPS during the test).

2.6 Power

The Samsung SSD SZ1735 is implemented in standardized 2.5-inch form factor and gets primary 12V power as well as auxiliary 3.3V (3.3Vaux) power through the indicated pins (#P13~15 for 12V and #E3 for 3.3Vaux in SFF-8639 connector plug) from the host system. For 12V and 3.3Vaux, the allowable voltage tolerance and noise level in SSD are described in chapter 2.6.1, the power consumption in 2.6.2 and the inrush current in 2.6.3.

2.6.1 Maximum Voltage Ratings (12V and 3.3Vaux)

[Table 8] Allowable Voltage Tolerance¹

| Operating Voltage | 800GB/1.6TB/3.2TB |
|--|--|
| 12V ² | 10% |
| 12V Rise time (Max/Min) | 50ms/1ms |
| 12V Fall time (Max/Min) ⁴ | 5s/1ms |
| 12V Noise level | 300 mV pp 10Hz – 100 KHz 50 mV pp 100KHz – 20 MHz |
| 3.3Vaux ³ | 10% |
| 3.3Vaux Rise time (Max/Min) | 50ms/1ms |
| 3.3Vaux Fall time (Max/Min) ⁴ | 5s/1ms |
| 3.3Vaux Noise level | 300 mV pp 10Hz – 100 KHz 50 mV pp 100KHz – 20 MHz |

NOTE:
 1) The components inside SSD were designed to endure the range of voltage fluctuations, which might be induced by the host system, in Table 8.
 2) For 12V operating voltage, the minimum allowable is 10.8V and the maximum 13.2V.
 3) For 3.3Vaux, the minimum allowable voltage is 2.97V and the maximum 3.63V.
 4) Fall time needs to be equal or better than minimum in order to guarantee full functionality of enhanced power loss management.

2.6.2 Power Consumption (12V)

In enterprise server and storage system, the Samsung SSD SZ1735 is designed for the specific usage, which means that SSD will be always operated by the host system during the entire life. Hence, the Samsung SSD SZ1735 does not manage any low power modes except for the Active/Idle, Off mode.

[Table 9] Power Consumption (12V Supply Voltage)¹

| Power Mode | | 800GB/1.6TB/3.2TB |
|---------------------|-------|-------------------|
| Active ² | Read | 11.5W |
| | Write | 12W |
| Idle ³ | | 5W |
| Off | | 0W |

NOTE:

- 1) Power consumption was measured in the 12V power pins (#P13~#P15) of the connector plug in SSD. The active and idle power is defined as the highest averaged power value, which is the maximum RMS average value over 100 ms duration.
- 2) The measurement condition for active power is assumed for 100% sequential read or write.
- 3) The idle state is defined as the state that the host system can issue any commands into SSD at any time.

2.7 Reliability

The reliability specification of the Samsung SSD SZ1735 follows JEDEC standard, which are included in JESD218A and JESD219A documents.

2.7.1 Mean Time Between Failures

By definition, Mean Time between Failures (MTBF) is the estimated time between failures occurring during SSD operation.

[Table 10] MTBF Specifications

| Parameter | 800GB/1.6TB/3.2TB |
|-----------|-------------------|
| MTBF | 2,000,000 Hours |

2.7.2 Uncorrectable Bit Error Rate

By definition, Uncorrectable Bit Error Rate (UBER) is a metric for the rate of occurrence of data errors, equal to the number of data errors per bits read as specified in the JESD218 document of JEDEC standard.

[Table 11] UBER Specifications

| Parameter | 800GB/1.6TB/3.2TB |
|-----------|---|
| UBER | 1 sector per 10 ¹⁷ bits read |

NOTE:

- 1) For the enterprise application, JEDEC recommends that UBER shall be below 10⁻¹⁶

2.7.3 Data Retention

By definition, data retention is the expected time period for retaining data in the SSD at the maximum rated endurance in power-off state as specified in the JESD218 document of JEDEC standard.

[Table 12] Data Retention

| Parameter | 800GB/1.6TB/3.2TB |
|-----------------------------|-------------------|
| Data Retention ¹ | 3 months |

NOTE:

- 1) Data retention was measured by assuming that SSD reaches the maximum rated endurance at 40C in power-off state.

2.7.4 Endurance

By definition, the endurance of SSD in enterprise application is defined as the maximum number of drive writes per day that can meet the requirements specified in the JESD218 document of JEDEC standard.

[Table 13] Drive Write Per Day (DWPD)

| Parameter | 800GB/1.6TB/3.2TB |
|-----------|-------------------|
|-----------|-------------------|

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| | |
|------|--------------------------------------|
| DWPD | 30 drive writes per day over 5 years |
|------|--------------------------------------|

[Table 14] Petabyte Written (PBW)

| Parameter | Unit | 800GB | 1.6TB | 3.2TB |
|-----------|------|-------|-------|-------|
| PBW | PB | 43.8 | 87.6 | 175.2 |

NOTE:
 1) Relational formula between DWPD and PBW is like below:
 PBW = DWPD x 365 x 5 x User capacity

2.8 Hot Plug Support

2.8.1 Power Loss Protection

By using internal back-up power technology, the Samsung SSD SZ1735 supports power loss protection (PLP) feature to guarantee the reliability of data requested by the host system. When power is unpredictably lost, SSD can detect automatically this abnormal situation and transfer all user data and meta-data cached in DRAM into the Flash media during any SSD operations.

2.8.2 Inrush Current Protection

When the Samsung SSD SZ1735 plugs in the backplane of host system, the significant amount of current is induced through 12V power rail. The Samsung SSD SZ1735 has protection circuitry including a set of resistors and capacitors to alleviate the impact by inrush current through 12V power.

[Table 15] Inrush Current

| Inrush Current | 800GB/1.6TB/3.2TB |
|----------------|--------------------|
| 12 V | 1.5A ¹⁾ |

NOTE:
 1) The measurement value of inrush current is also compatible with the standard specification of "Enterprise SSD Form Factor Version 1.0a" released by SSD Form Factor Working Group.

2.9 Environmental Specification

2.9.1 Temperature

[Table 16] Temperature

| Temperature ¹⁾ | 800GB/1.6TB/3.2TB | |
|---------------------------|-------------------|-----------------------------|
| | Operating | Non-Operating ²⁾ |
| | 0 to 70 °C | -40 to 85 °C |

NOTE:
 1) Temperature of the hottest point on the case (Tc). The device will be working properly within the operating temperature range without deteriorating device long-term reliability and any throttling. Sufficient airflow would be recommended to be operated properly on any heavier workloads within device operating temperature.
 2) Unbiased state

2.9.2 Humidity

[Table 17] Humidity

| Humidity ¹⁾ | | 800GB/1.6TB/3.2TB |
|------------------------|---------------|-------------------|
| | Non-operating | 5% to 95% |

NOTE:
 1) Humidity is measured in non-condensing state.

2.9.3 Shock and Vibration

[Table 18] Shock and Vibration

| | | 800GB/1.6TB/3.2TB |
|-------------------------|---------------|-----------------------------------|
| Shock ¹⁾ | Non-operating | 1,500G |
| Vibration ²⁾ | Non-operating | 20 Gpeak (10~2,000Hz, Sweep sine) |

NOTE:
 1) Shock specifications assume that SSD shall be mounted with screws when input vibration is applied. Vibration may be applied in 3 axes (x, y and z) with a half sine waveform of 0.5ms duration in non-operating condition.
 2) Vibration specifications assume that SSD shall be mounted with screws when input vibration is applied. The input vibration may be applied in 3 axes (x, y and z) and lasts during 15 minutes per axis.

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3.0 MECHANICAL SPECIFICATIONS

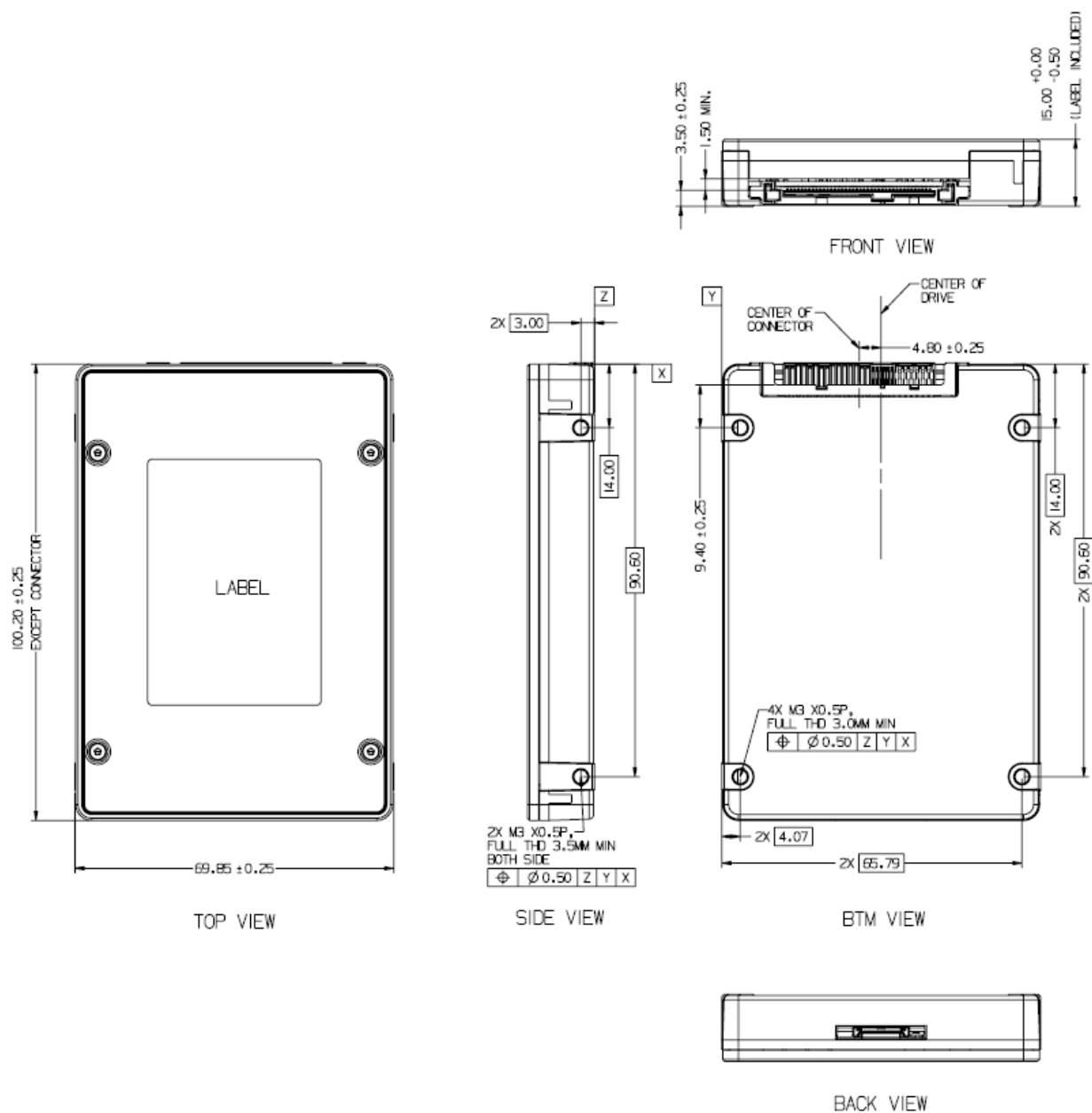
3.1 Physical Information

The physical case of the Samsung SSD SZ1735 in 2.5-inch form factor follows the standardized dimensions defined by SSD Form Factor Work Group.

[Table 19] Physical Dimensions and Weight

| Parameter | Unit | 800GB/1.6TB/3.2TB |
|-----------|------|-------------------|
| Width | mm | 69.85±0.25 |
| Length | mm | 100.20±0.25 |
| Thickness | mm | 14.80±0.20 |
| Weight | g | Up to 190g |

Figure 1. Mechanical Outline



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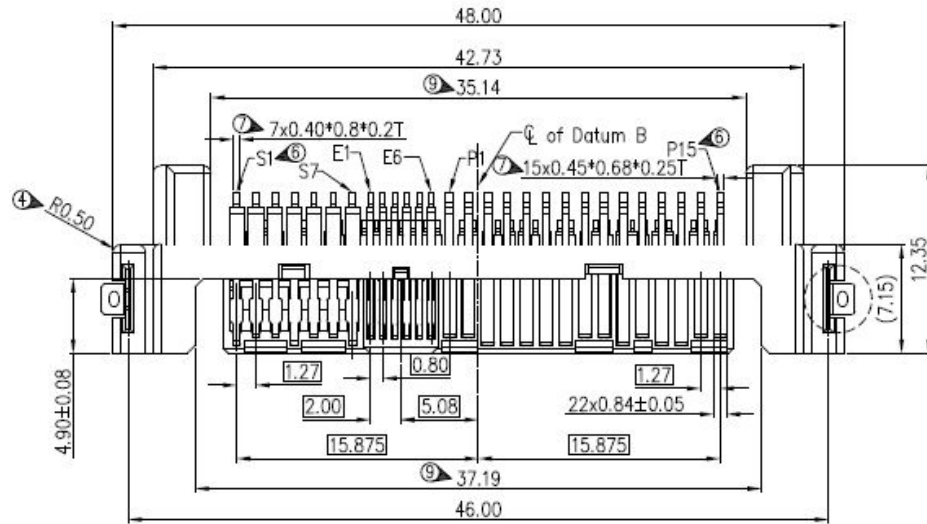
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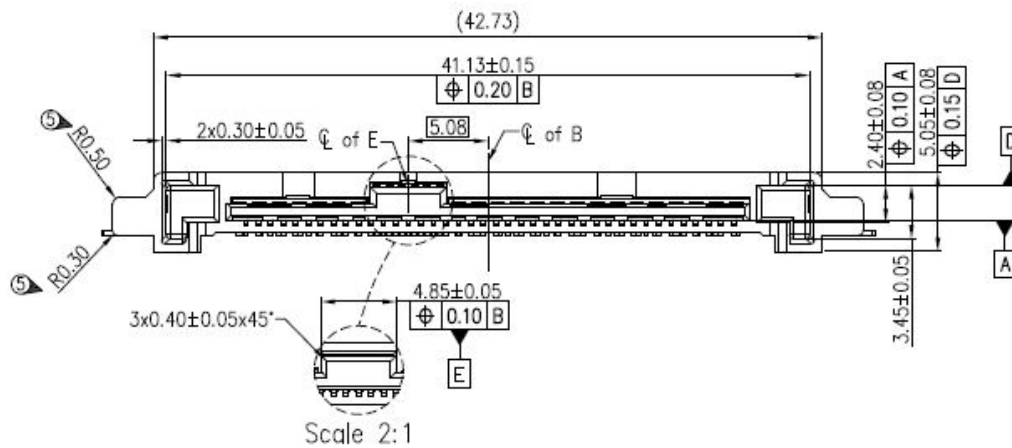
4.0 INTERFACE SPECIFICATION

The PCIe connector of SZ1735 is compliant with SFF-8639 standard specification.

4.1 Connector Dimensions



<Top View>



<Bottom View>

Figure 1. Layout of 2.5-inch Form Factor Connector Pins

4.2 Connector Pin Assignments

[Table 20] Certifications and Declarations

| Pin # | Assignment | Description | Pin # | Assignment | Description |
|-------|------------|--|-------|-------------|---|
| S1 | Not Used | Float | E7 | RefClk0+ | PCIe Reference Clock + (primary port A) |
| S2 | Not Used | | E8 | RefClk0- | PCIe Reference Clock - (primary port A) |
| S3 | Not Used | | E9 | GND | Ground |
| S4 | Not Used | Ground | E10 | PETp0 | PCIe Transmit+ (lane 0) |
| S5 | Not Used | | E11 | PETn0 | PCIe Transmit- (lane 0) |
| S6 | Not Used | | E12 | GND | Ground |
| S7 | Not Used | Ground | E13 | PERn0 | PCIe Receive- (lane 0) |
| E1 | REFCLK1+ | PCIe Reference Clock + (dual port, port B) | E14 | PERp0 | PCIe Receive+ (lane 0) |
| E2 | REFCLK1- | PCIe Reference Clock - (dual port, port B) | E15 | GND | Ground |
| E3 | 3.3V AUX | Auxiliary Power (for SMBus access) | E16 | Not Used | |
| E4 | ePERST1# | PCIe Reset (dual port, port B) | S8 | Not Used | Ground |
| E5 | ePERST0# | PCIe Reset (primary port A) | S9 | Not Used | |
| E6 | Not Used | | S10 | Not Used | |
| P1 | Not Used | | S11 | Not Used | Ground |
| P2 | Not Used | | S12 | Not Used | |
| P3 | Not Used | | S13 | Not Used | |
| P4 | IfDet # | Interface Detect | S14 | Not Used | Ground |
| P5 | GND | Ground | S15 | Not Used | |
| P6 | GND | Ground | S16 | GND | Ground |
| P7 | Not Used | | S17 | PETp1 | PCIe Transmit+ (lane 1) |
| P8 | Not Used | | S18 | PETn1 | PCIe Transmit- (lane 1) |
| P9 | Not Used | | S19 | GND | Ground |
| P10 | PRSNT # | Presence | S20 | PERn1 | PCIe Receive- (lane 1) |
| P11 | Activity | Drive Active | S21 | PERp1 | PCIe Receive+ (lane 1) |
| P12 | GND | Ground | S22 | GND | Ground |
| P13 | 12 V | Primary Power | S23 | PETp2 | PCIe Transmit+ (lane 2) |
| P14 | 12 V | Primary Power | S24 | PETn2 | PCIe Transmit- (lane 2) |
| P15 | 12 V | Primary Power | S25 | GND | Ground |
| | | | S26 | PERn2 | PCIe Receive- (lane 2) |
| | | | S27 | PERp2 | PCIe Receive+ (lane 2) |
| | | | S28 | GND | Ground |
| | | | E17 | PETp3 | PCIe Transmit+ (lane 3) |
| | | | E18 | PETn3 | PCIe Transmit- (lane 3) |
| | | | E19 | GND | Ground |
| | | | E20 | PERn3 | PCIe Receive- (lane 3) |
| | | | E21 | PERp3 | PCIe Receive+ (lane 3) |
| | | | E22 | GND | Ground |
| | | | E23 | SMClk | SMBus Clock |
| | | | E24 | SMDat | SMBus Data |
| | | | E25 | DualPortEn# | Dual Port PCIe enable |

5.0 PCI AND NVM EXPRESS REGISTERS

5.1 PCI Express Registers

5.1.1 PCI Register Summary

[Table 21] PCI Register Summary

| Start Address | Tag | Name | Type |
|---------------|-----------|--|--------------------------------|
| 00h | TYPE0_HDR | PCI Header | PCI Configuration Header Space |
| 40h | PM_CAP | PCI Power Management Capability | PCI Capability |
| 50h | MSI_CAP | MSI Capability | PCI Capability |
| 70h | PCIE_CAP | PCI Express Capability | PCI Capability |
| B0h | MSIX_CAP | MSI-X Capability | PCI Capability |
| 100h | AER_CAP | Advanced Error Reporting (AER) Capability | PCIe Extended Capability |
| 178h | SPCIE_CAP | Secondary PCI Express Capability (Gen3) Capability | PCIe Extended Capability |

5.1.2 PCI Header Registers

5.1.2.1 PCI Configuration Header Space Registers

[Table 22] PCI Header Space Summary

| Start Address | End Address | Symbol | Description |
|---------------|-------------|--------------|---|
| 00h | 03h | ID | Identifiers |
| 04h | 05h | CMD | Command Register |
| 06h | 07h | STS | Status Register |
| 08h | 08h | REVID | Revision ID |
| 09h | 0Bh | CC | Class Codes |
| 0Ch | 0Ch | CLS | Cache Line Size |
| 0Dh | 0Dh | MLT | Master Latency Timer |
| 0Eh | 0Eh | HTYPE | Header Type |
| 0Fh | 0Fh | BIST | Built in Self Test |
| 10h | 13h | MLBAR (BAR0) | Memory Register Base Address (lower 32-bit) |
| 14h | 17h | MUBAR (BAR1) | Memory Register Base Address (upper 32-bit) |
| 18h | 1Bh | IDBAR (BAR2) | Reserved |
| 1Ch | 1Fh | BAR3 | Reserved |
| 20h | 23h | BAR4 | Reserved |
| 24h | 27h | BAR5 | Reserved |
| 28h | 2Bh | CCPTR | CardBus CIS Pointer |
| 2Ch | 2Fh | SS | Subsystem Identifiers |
| 30h | 33h | EXPROM | Expansion ROM Base Address |
| 34h | 34h | CAP | Capabilities Pointer |
| 35h | 3Bh | R | Reserved |
| 3Ch | 3Dh | INTR | Interrupt Information |
| 3Eh | 3Eh | MGNT | Minimum Grant |
| 3Fh | 3Fh | MLAT | Maximum Latency |

[Table 23] Identifier Register

| Bits | Type | Default Value | Description |
|-------|------|---------------|-------------|
| 31:16 | RO | A822h | Device ID |
| 0:15 | RO | 144Dh | Vendor ID |

[Table 24] Command Register

| Bits | Type | Default Value | Description |
|-------|------|---------------|---|
| 15:11 | RO | 0 | Reserved |
| 10 | RW | 0 | Interrupt Disable |
| 9 | RO | 0 | Fast Back-to-Back Enable (N/A) |
| 8 | RW | 0 | SERR# Enable |
| 7 | RO | 0 | IDSEL Stepping / Wait Cycle Control (N/A) |
| 6 | RW | 0 | Parity Error Response Enable |
| 5 | RO | 0 | VGA Palette Snooping Enable (N/A) |
| 4 | RO | 0 | Memory Write and Invalidate Enable (N/A) |
| 3 | RO | 0 | Special Cycle Enable (N/A) |
| 2 | RW | 0 | Bus Master Enable |
| 1 | RW | 0 | Memory Space Enable |
| 0 | RW | 0 | I/O Space Enable |

[Table 25] Status Register

| Bits | Type | Default Value | Description |
|------|------|---------------|-----------------------------------|
| 15 | RW1C | 0 | Detected Parity Error |
| 14 | RW1C | 0 | Signaled System Error |
| 13 | RW1C | 0 | Received Master Abort |
| 12 | RW1C | 0 | Received Target Abort |
| 11 | RW1C | 0 | Signaled Target Abort (N/A) |
| 10:9 | RO | 0 | DEVSEL Timing (N/A) |
| 8 | RW1C | 0 | Master Data Parity Error Detected |
| 7 | RO | 0 | Fast Back-To-Back Capable (N/A) |
| 6 | RO | 0 | Reserved |
| 5 | RO | 0 | 66MHz Capable (N/A) |
| 4 | RO | 1 | Capabilities List |
| 3 | RO | 0 | Interrupt Status |
| 2:1 | RO | 0 | Reserved |
| 0 | RO | 0 | Reserved |

[Table 26] Revision ID Register

| Bits | Type | Default Value | Description |
|------|------|---------------|---------------------------------|
| 7:0 | RO | 00h | Controller Hardware Revision ID |

[Table 27] Class Code Register

| Bits | Type | Default Value | Description |
|-------|------|---------------|-----------------------|
| 23:16 | RO | 01h | Base Class Code |
| 15:8 | RO | 08h | Sub Class Code |
| 7:0 | RO | 02h | Programming Interface |

[Table 28] Cache Line Size Register

| Bits | Type | Default Value | Description |
|------|------|---------------|-----------------------|
| 7:0 | RW | 0 | Cache Line Size (N/A) |

IF THERE IS ANY OTHER OPERATION TO IMPLEMENT IN ADDITION TO SPECIFICATION IN THE DATASHEET OR JEDEC STANDARD, PLEASE CONTACT EACH BRANCH OFFICE OR HEADQUARTERS OF SAMSUNG ELECTRONICS.

[Table 29] Master Latency Timer Register

| Bits | Type | Default Value | Description |
|------|------|---------------|----------------------------|
| 7:0 | RO | 0 | Master Latency Timer (N/A) |

[Table 30] Header Type Register

| Bits | Type | Default Value | Description |
|------|------|---------------|-----------------------------|
| 7 | RO | 0 | Multi-Function Device (N/A) |
| 6:0 | RO | 0 | Reserved |

[Table 31] Built In Self Test Register

| Bits | Type | Default Value | Description |
|------|------|---------------|--------------------------|
| 7 | RO | 0 | Built In Self Test (N/A) |
| 6 | RO | 0 | Built In Self Test (N/A) |
| 5:4 | RO | 0 | Built In Self Test (N/A) |
| 3:0 | RO | 0 | Built In Self Test (N/A) |

[Table 32] Memory Register Base Address Lower 32-bits (BAR0) Register

| Bits | Type | Default Value | Description |
|-------|------|---------------|--------------------------------|
| 31:15 | RW | 0 | Base Address |
| 14:4 | RO | 0 | Reserved |
| 3 | RO | 0 | Pre-Fetchable |
| 2:1 | RO | 2h | Address Type (64-bit) |
| 0 | RO | 0 | Memory Space Indicator (MEMSI) |

[Table 33] Memory Register Base Address Upper 32-bits (BAR1)

| Bits | Type | Default Value | Description |
|------|------|---------------|--------------|
| 31:0 | RW | 0 | Base Address |

[Table 34] Memory Register Base Address (BAR2) Register

| Bits | Type | Default Value | Description |
|------|------|---------------|-------------|
| 31:0 | RO | 0 | N/A |

[Table 35] BAR3 Register

| Bits | Type | Default Value | Description |
|------|------|---------------|-------------|
| 31:0 | RO | 0 | N/A |

[Table 36] Vendor Specific BAR4 Register

| Bits | Type | Default Value | Description |
|------|------|---------------|-------------|
| 31:0 | RO | 0 | N/A |

[Table 37] Vendor Specific BAR5 Register

| Bits | Type | Default Value | Description |
|------|------|---------------|-------------|
| 31:0 | RO | 0 | N/A |

[Table 38] Cardbus CIS Pointer Register

| Bits | Type | Default Value | Description |
|------|------|---------------|-------------|
| 31:0 | RO | 0 | N/A |

IF THERE IS ANY OTHER OPERATION TO IMPLEMENT IN ADDITION TO SPECIFICATION IN THE DATASHEET OR JEDEC STANDARD, PLEASE CONTACT EACH BRANCH OFFICE OR HEADQUARTERS OF SAMSUNG ELECTRONICS.

[Table 39] Subsystem Identifier Register

| Bits | Type | Default Value | Description |
|-------|------|---------------|---------------------|
| 31:16 | RO | A801h | Subsystem ID |
| 15:0 | RO | 144Dh | Subsystem Vendor ID |

[Table 40] Expansion ROM Register

| Bits | Type | Default Value | Description |
|-------|------|---------------|------------------------------|
| 31:17 | RW | 0 | Expansion ROM Base Address |
| 16:1 | RO | 0 | Reserved |
| 0 | RW | 0 | Expansion ROM Enable/Disable |

[Table 41] Capabilities Pointer Register

| Bits | Type | Default Value | Description |
|------|------|---------------|--------------------|
| 7:0 | RO | 40h | Capability Pointer |

[Table 42] Interrupt Information Register

| Bits | Type | Default Value | Description |
|------|------|---------------|----------------|
| 15:8 | RO | 01h | Interrupt Pin |
| 7:0 | RW | FFh | Interrupt Line |

[Table 43] Minimum Grant Register

| Bits | Type | Default Value | Description |
|------|------|---------------|---------------------|
| 7:0 | RO | 0 | Minimum Grant (N/A) |

[Table 44] Maximum Latency Register

| Bits | Type | Default Value | Description |
|------|------|---------------|-----------------------|
| 7:0 | RO | 0 | Maximum Latency (N/A) |

5.1.3 PCI Capability Registers Detail

5.1.3.1 PCI Power Management Capability

[Table 45] PCI Power Management Capability Summary

| Start Address | End Address | Symbol | Description |
|---------------|-------------|---------------|---|
| 40h | 40h | PCIPM_ID | PCI Power Management Capability ID |
| 41h | 41h | NEXTCAP | Next Capability Pointer |
| 42h | 43h | PCIPM_CAP | PC Power Management Capabilities |
| 44h | 45h | PCIPM_CS | PCI Power Management Control and Status |
| 46h | 46h | PCIPM_CSR_BSE | PMCSR_BSE Bridge Extensions |
| 47h | 47h | PCIPM_DATA | Data |

[Table 46] PCI Power Management Capability ID Register

| Bits | Type | Default Value | Description |
|------|------|---------------|-------------------------|
| 15:8 | RO | 50h | Next Capability Pointer |
| 7:0 | RO | 1h | Capability ID |

IF THERE IS ANY OTHER OPERATION TO IMPLEMENT IN ADDITION TO SPECIFICATION IN THE DATASHEET OR JEDEC STANDARD, PLEASE CONTACT EACH BRANCH OFFICE OR HEADQUARTERS OF SAMSUNG ELECTRONICS.

[Table 47] PCI Power Management Capability Register

| Bits | Type | Default Value | Description |
|-------|-------|---------------|--|
| 15:11 | RO | 0 | PME Support (N/A) |
| 10 | RO | 0 | D2 Support (N/A) |
| 9 | RO | 0 | D1 Support (N/A) |
| 8:6 | RO | 0 | AUX current (N/A) |
| 5 | RO | 0 | Device Specific Initialization (N/A) |
| 4 | RsvdP | 0 | Reserved |
| 3 | RO | 0 | PME Clock (N/A) |
| 2:0 | RO | 3h | Version (Support for PCIe Power Management Interface Spec Rev. 1.2) |

[Table 48] PCI Power Management Control and Status Register

| Bits | Type | Default Value | Description |
|-------|-------|---------------|--------------------------------|
| 31:24 | RsvdP | 0 | Data register (N/A) |
| 23 | RO | 0 | Bus Power / Clock Enable (N/A) |
| 22 | RO | 0 | B2, B3 Support (N/A) |
| 21:16 | RsvdP | 0 | Reserved |
| 15 | RO | 0 | PME Status (N/A) |
| 14:13 | RO | 0 | Data Scale (N/A) |
| 12:9 | RO | 0 | Data Scale (N/A) |
| 8 | RWS | 0 | PME Enable (N/A) |
| 7:4 | RsvdP | 0 | Reserved |
| 3 | RO | 1 | No Soft Reset |
| 2 | RsvdP | 0 | Reserved |
| 1:0 | RW | 0 | Power State |

5.1.3.2 Message Signaled Interrupt (MSI) Registers

[Table 49] Message Signaled Interrupt Capability Summary

| Start Address | End Address | Symbol | Description |
|---------------|-------------|-----------|--|
| 50h | 51h | MSI_ID | Message Signaled Interrupt Capability ID |
| 52h | 53h | MSI_MC | Message Signaled Interrupt Message Control |
| 54h | 57h | MSI_MA | Message Signaled Interrupt Message Address |
| 58h | 5Bh | MSI_MUA | Message Signaled Interrupt Upper Address |
| 5Ch | 5Dh | MSI_MDATA | Message Signaled Interrupt Message Data |
| 60h | 63h | MSI_MMASK | Message Signaled Interrupt Mask Bits |
| 64h | 67h | MSI_MPEND | Message Signaled Interrupt Pending Bits |

[Table 50] Message Signaled Interrupt Capability ID Register

| Bits | Type | Default Value | Description |
|------|------|---------------|-------------------------|
| 15:8 | RO | 70h | Next Capability Pointer |
| 7:0 | RO | 05h | Capability ID |

[Table 51] Message Signaled Interrupt Control Register

| Bits | Type | Default Value | Description |
|------|-------|---------------|----------------------------------|
| 15:9 | RsvdP | 0 | Reserved |
| 8 | RO | 0 | Per Vector Masking Capable (N/A) |
| 7 | RO | 1h | 64-bit Address Capable |
| 6:4 | RW | 0 | Multiple Message Enable |
| 3:1 | RO | 5h | Multiple Message Capable |
| 0 | RW | 0 | MSI Enable |

[Table 52] Message Signaled Interrupt Address Register

| Bits | Type | Default Value | Description |
|------|-------|---------------|-------------|
| 31:2 | RW | 0 | Address |
| 1:0 | RsvdP | 0 | Reserved |

[Table 53] Message Signaled Interrupt Upper Address Register

| Bits | Type | Default Value | Description |
|------|------|---------------|---------------|
| 31:0 | RW | 0 | Upper Address |

[Table 54] Message Signaled Interrupt Message Data Register

| Bits | Type | Default Value | Description |
|-------|-------|---------------|-------------|
| 31:16 | RsvdP | 0 | Reserved |
| 15:0 | RW | 0 | Data |

[Table 55] Message Signaled Interrupt Mask Bits Register

| Bits | Type | Default Value | Description |
|------|------|---------------|-----------------|
| 31:0 | RW | 0 | Mask Bits (N/A) |

[Table 56] Message Signaled Interrupt Pending Bits Register

| Bits | Type | Default Value | Description |
|------|------|---------------|--------------|
| 31:0 | RO | 0 | Pending Bits |

5.1.3.3 MSI-X Capability

[Table 57] MSI-X Capability Register Summary

| Start Address | End Address | Symbol | Description |
|---------------|-------------|----------|----------------------------------|
| B0h | B1h | MSIX_ID | MSI-X Capability ID |
| B2h | B3h | MSIX_CAP | MSI-X Message Control |
| B4h | B7h | MSIX_TBL | MSI-X Table Offset and Table BIR |
| B8h | BBh | MSIX_PBA | MSI-X PBA Offset and PBA BIR |

[Table 58] MSI-X Capability ID Register

| Bits | Type | Default Value | Description |
|------|------|---------------|-------------------------|
| 15:8 | RO | 00h | Next Capability Pointer |
| 7:0 | RO | 11h | Capability ID |

[Table 59] MSI-X Control Register

| Bits | Type | Default Value | Description |
|-------|-------|---------------|---------------|
| 15 | RW | 0 | MSI-X Enable |
| 14 | RW | 0 | Function Mask |
| 13:11 | RsvdP | 0 | Reserved |
| 10:0 | RO | 243h | Table Size |

[Table 60] MSI-X Table Offset Register

| Bits | Type | Default Value | Description |
|------|------|---------------|--------------|
| 31:3 | RO | 800h | Table Offset |
| 2:0 | RO | 0 | Table BIR |

[Table 61] MSI-X Pending Bit Array Offset Register

| Bits | Type | Default Value | Description |
|------|------|---------------|--------------------------|
| 31:3 | RO | 600h | Pending Bit Array Offset |
| 2:0 | RO | 0 | Pending Bit Array BIR |

5.1.3.4 PCI Express Capability Registers

[Table 62] PCI Express Capability Register Summary

| Start Address | End Address | Symbol | Description |
|---------------|-------------|------------|-----------------------------------|
| 70h | 71h | PCIe_ID | PCI Express Capability ID |
| 72h | 73h | PCIe_CAP | PCI Express Capabilities |
| 74h | 77h | PCIe_DCAP | PCI Express Device Capabilities |
| 78h | 79h | PCIe_DC | PCI Express Device Control |
| 7Ah | 7Bh | PCIe_DS | PCI Express Device Status |
| 7Ch | 7Fh | PCIe_LCAP | PCI Express Link Capabilities |
| 80h | 81h | PCIe_LC | PCI Express Link Control |
| 82h | 83h | PCIe_LS | PCI Express Link Status |
| 94h | 97h | PCIe_DCAP2 | PCI Express Device Capabilities 2 |
| 98h | 99h | PCIe_DC2 | PCI Express Device Control 2 |
| 9Ah | 9Bh | PCIe_DS2 | PCI Express Device Status 2 |
| 9Ch | 9Fh | PCIe_LCAP2 | PCI Express Link Capabilities 2 |
| A0h | A1h | PCIe_LC2 | PCI Express Link Control 2 |
| A2h | A3h | PCIe_LS2 | PCI Express Link Status 2 |

[Table 63] PCI Express Capability ID Register

| Bits | Type | Default Value | Description |
|------|------|---------------|-------------------------|
| 15:8 | RO | B0h | Next Capability Pointer |
| 7:0 | RO | 10h | Capability ID |

[Table 64] PCI Express Capabilities Register

| Bits | Type | Default Value | Description |
|-------|--------|---------------|---------------------------|
| 15:14 | RsvdP | 0 | Reserved |
| 13:9 | RO | 0 | Interrupt Message Number |
| 8 | HwInit | 0 | Slot Implementation (N/A) |
| 7:4 | RO | 0 | Device/Port Type |
| 3:0 | RO | 2h | Capability Version |

[Table 65] PCI Express Device Capabilities Register

| Bits | Type | Default Value | Description |
|-------|-------|---------------|---------------------------------|
| 31:29 | RsvdP | 0 | Reserved |
| 28 | RO | 1 | Function Level Reset Capability |
| 27:26 | RO | 0 | Captured Slot Power Limit Scale |
| 25:18 | RO | 0 | Captured Slot Power Limit Value |
| 17:16 | RsvdP | 0 | Reserved |
| 15 | RO | 1 | Role-based Error Reporting |
| 14:12 | RO | 0 | Reserved |
| 11:9 | RO | 7h | Endpoint L1 Acceptable Latency |
| 8:6 | RO | 7h | Endpoint L0 Acceptable Latency |
| 5 | RO | 0 | Extended Tag Field Supported |
| 4:3 | RO | 0 | Phantom Functions Supported |
| 2:0 | RO | 2h | Max Payload Size Supported |

[Table 66] PCI Express Device Control Register

| Bits | Type | Default Value | Description |
|-------|------|---------------|--------------------------------------|
| 15 | RW | 0 | Initiate Function Level Reset |
| 14:12 | RW | 2h | Max Read Request Size |
| 11 | RW | 1 | Enable No Snoop |
| 10 | RWS | 0 | Aux Power PM Enable (N/A) |
| 9 | RW | 0 | Phantom Functions Enable (N/A) |
| 8 | RW | 0 | Extended Tag Enable |
| 7:5 | RW | 0 | Max Payload Size |
| 4 | RW | 1 | Enable Relaxed Ordering |
| 3 | RW | 0 | Unsupported Request Reporting Enable |
| 2 | RW | 0 | Fatal Error Reporting Enable |
| 1 | RW | 0 | Non-Fatal Error Reporting Enable |
| 0 | RW | 0 | Correctable Error Reporting Enable |

[Table 67] PCI Express Device Status Register

| Bits | Type | Default Value | Description |
|------|-------|---------------|------------------------------|
| 15:6 | RsvdZ | 0 | Reserved |
| 5 | RO | 0 | Transactions Pending |
| 4 | RO | 0 | Aux Power Detected |
| 3 | RW1C | 0 | Unsupported Request Detected |
| 2 | RW1C | 0 | Fatal Error Detected |
| 1 | RW1C | 0 | Non-Fatal Error Detected |
| 0 | RW1C | 0 | Correctable Error Detected |

[Table 68] PCI Express Link Capabilities Register

| Bits | Type | Default Value | Description |
|-------|--------|---------------|---|
| 31:24 | Hwlnit | 0 (Port 0) | Port Number |
| 23 | RsvdP | 0 | Reserved |
| 22 | Hwlnit | 1 | ASPM Optionality Compliance |
| 21 | RO | 0 | Link Bandwidth Notification Capability (N/A) |
| 20 | RO | 0 | Data Link Layer Link Active Reporting Capable (N/A) |
| 19 | RO | 0 | Surprise Down Error Reporting Capable (N/A) |

IF THERE IS ANY OTHER OPERATION TO IMPLEMENT IN ADDITION TO SPECIFICATION IN THE DATASHEET OR JEDEC STANDARD, PLEASE CONTACT EACH BRANCH OFFICE OR HEADQUARTERS OF SAMSUNG ELECTRONICS.

| | | | |
|-------|----|--------------|---------------------------------------|
| 18 | RO | 0 | Clock Power Management |
| 17:15 | RO | 6h | L1 Exit Latency |
| 14:12 | RO | 7h | LOs Exit Latency |
| 11:10 | RO | 0 | Active State Power Management Support |
| 9:4 | RO | 4h (x4 link) | Maximum Link Width |
| 3:0 | RO | 3h | Supported Link Speeds |

[Table 69] PCI Express Link Control Register

| Bits | Type | Default Value | Description |
|-------|----------|---------------|--|
| 15:14 | RW/RsvdP | 0h | Reserved |
| 13:12 | RsvdP | 0 | Reserved |
| 11 | RsvdP | 0 | Link Autonomous Bandwidth interrupt enable (N/A) |
| 10 | RsvdP | 0 | Link Bandwidth management interrupt enable (N/A) |
| 9 | RW | 0 | Hardware Autonomous Width Disable |
| 8 | RW | 0 | Enable Clock Power Management |
| 7 | RW | 0 | Extended Sync |
| 6 | RW | 0 | Common Clock Configuration |
| 5 | RsvdP | 0 | Retrain Link (N/A) |
| 4 | RsvdP | 0 | Link Disable (N/A) |
| 3 | RW | 0 | Read Completion Boundary (N/A) |
| 2 | RsvdP | 0 | Reserved |
| 1:0 | RW | 0 | Active State Power Management Control |

[Table 70] PCI Express Link Status Register

| Bits | Type | Default Value | Description |
|------|--------|---------------|---|
| 15 | RsvdP | 0h | Link Autonomous Bandwidth Status (N/A) |
| 14 | RsvdP | 0 | Link Autonomous Management Status (N/A) |
| 13 | RO | 0 | Data Link Layer Link Active |
| 12 | HwInit | 1 | Slot Clock Configuration |
| 11 | RO | 0 | Link Training (N/A) |
| 10 | RO | 0 | Reserved |
| 9:4 | RO | 1h | Negotiated Link Width |
| 3:0 | RO | 1h | Current Link Speed |

[Table 71] PCI Express Device Capabilities 2 Register

| Bits | Type | Default Value | Description |
|-------|--------|---------------|---------------------------------------|
| 31 | HwInit | 0 | Reserved |
| 30:24 | RsvdP | 0 | Reserved |
| 23:22 | HwInit | 0 | Max End-End TLP Prefixes (N/A) |
| 21 | HwInit | 0 | End-End TLP Prefix Supported (N/A) |
| 20 | RO | 0 | Extended Format Field Supported (N/A) |
| 19:18 | HwInit | 0 | OBFF Supported (N/A) |
| 17:16 | RsvdP | 0 | Reserved |
| 15:14 | HwInit | 0 | LN System CLS (N/A) |
| 13:12 | RO | 0 | TPH Completer Supported (N/A) |
| 11 | RO | 0 | Latency Tolerance Reporting Supported |
| 10 | HwInit | 0 | No RO-enabled PR-PR Passing (N/A) |
| 9 | RO | 0 | 128-bit CAS Completer Supported (N/A) |

IF THERE IS ANY OTHER OPERATION TO IMPLEMENT IN ADDITION TO SPECIFICATION IN THE DATASHEET OR JEDEC STANDARD, PLEASE CONTACT EACH BRANCH OFFICE OR HEADQUARTERS OF SAMSUNG ELECTRONICS.

| | | | |
|-----|--------|----|--|
| 8 | RO | 0 | 64-bit Atomic Op Completer Supported (N/A) |
| 7 | RO | 0 | 32-bit Atomic Op Completer Supported (N/A) |
| 6 | RO | 0 | Atomic Op Routing Supported (N/A) |
| 5 | RO | 0 | ARI Forwarding Supported (N/A) |
| 4 | RO | 1 | Completion Timeout Disable Supported |
| 3:0 | Hwlnit | Fh | Completion Timeout Ranges Supported |

[Table 72] PCI Express Device Control 2 Register

| Bits | Type | Default Value | Description |
|-------|----------|---------------|--|
| 15 | RsvdP | 0 | End-to-end Prefix Blocking (N/A) |
| 14:13 | RW/RsvdP | 0 | OBFF Enable (N/A) |
| 12:11 | RsvdP | 0 | Reserved |
| 10 | RW/RsvdP | 0 | Latency Tolerance Reporting Mechanism Enable |
| 9 | RW | 0 | IDO Completion enable (N/A) |
| 8 | RW | 0 | IDO Request Enable (N/A) |
| 7 | RW | 0 | AtomicOp Egress Blocking (N/A) |
| 6 | RW | 0 | AtomicOp Requester Enable (N/A) |
| 5 | RW | 0 | ARI forwarding supported (N/A) |
| 4 | RW | 0 | Completion Timeout Disable |
| 3:0 | RW | 0 | Completion Timeout Value |

[Table 73] PCI Express Device Status 2 Register

| Bits | Type | Default Value | Description |
|------|-------|---------------|-------------|
| 15:0 | RsvdZ | 0 | Reserved |

[Table 74] PCI Express Link Capabilities 2 Register

| Bits | Type | Default Value | Description |
|-------|--------|---------------|--|
| 31 | RO | 0 | Reserved |
| 30:24 | RsvdP | 0 | Reserved |
| 23 | Hwlnit | 0 | Reserved |
| 22:16 | Hwlnit | 0 | Lower SKP OS Reception Supported Speed Vector (N/A) |
| 15:9 | Hwlnit | 0 | Lower SKP OS Generation Supported Speed Vector (N/A) |
| 8 | RO | 0 | Cross-Link Supported (N/A) |
| 7:1 | RO | 7h | Supported Speeds Vector |
| 0 | RsvdP | 0 | Reserved |

[Table 75] PCI Express Link Control 2 Register

| Bits | Type | Default Value | Description |
|-------|-----------|---------------|-----------------------------------|
| 15:12 | RWS/RsvdP | 0 | Compliance De-emphasis |
| 11 | RWS/RsvdP | 0 | Compliance SOS |
| 10 | RWS/RsvdP | 0 | Enter Modified Compliance |
| 9:7 | RWS/RsvdP | 0 | Transmit Margin |
| 6 | Hwlnit | 0 | Select De-Emphasis (N/A) |
| 5 | RWS/RsvdP | 0 | Hardware Autonomous Speed Disable |
| 4 | RWS/RsvdP | 0 | Enter Compliance |
| 3:0 | RWS/RsvdP | 3h | Target Link Speed |

IF THERE IS ANY OTHER OPERATION TO IMPLEMENT IN ADDITION TO SPECIFICATION IN THE DATASHEET OR JEDEC STANDARD, PLEASE CONTACT EACH BRANCH OFFICE OR HEADQUARTERS OF SAMSUNG ELECTRONICS.

[Table 76] PCI Express Link Status 2 Register

| Bits | Type | Default Value | Description |
|------|-------|---------------|---|
| 15:6 | RsvdP | 0 | Reserved |
| 5 | RW1CS | 0 | Link Equalization Request |
| 4 | ROS | 0 | Equalization 8.0GT/s Phase 3 Successful |
| 3 | ROS | 0 | Equalization 8.0GT/s Phase 2 Successful |
| 2 | ROS | 0 | Equalization 8.0GT/s Phase 1 Successful |
| 1 | ROS | 0 | Equalization Complete |
| 0 | RO | 1 | Current De-Emphasis |

5.1.4 PCI Extended Capability Details

5.1.4.1 Advanced Error Reporting Registers

[Table 77] Advanced Error Reporting Capability Summary

| Start Address | End Address | Symbol | Description |
|---------------|-------------|------------|---|
| 100h | 103h | AER_ID | AER Capability ID |
| 104h | 107h | AER_UCES | AER Uncorrectable Error Status |
| 108h | 10Bh | AER_UCEM | AER Uncorrectable Error Mask |
| 10Ch | 10Fh | AER_UCESEV | AER Uncorrectable Error Severity |
| 110h | 113h | AER_CES | AER Correctable Error Status |
| 114h | 117h | AER_CEM | AER Correctable Error Mask |
| 118h | 11Bh | AER_CC | AER Advanced Error Capabilities and Control |
| 11Ch | 12Bh | AER_HL | AER Header Log |

[Table 78] AER Capability ID Register

| Bits | Type | Default Value | Description |
|-------|------|---------------|------------------------------------|
| 31:20 | RO | 178h | Next Capability Pointer |
| 19:16 | RO | 2h | Capability Version |
| 15:0 | RO | 1h | PCI Express Extended Capability ID |

[Table 79] AER Uncorrectable Error Status Register

| Bits | Type | Default Value | Description |
|-------|-------|---------------|--|
| 31:27 | RsvdZ | 0 | Reserved |
| 26 | RW1CS | 0 | Poisoned TLP Egress Blocked Status (N/A) |
| 25 | RW1CS | 0 | TLP Prefix Blocked Error Status (N/A) |
| 24 | RW1CS | 0 | Atomic Op Egress Blocked Status (N/A) |
| 23 | RW1CS | 0 | MC Blocked TLP Status (N/A) |
| 22 | RW1CS | 0 | Uncorrectable Internal Error Status |
| 21 | RW1CS | 0 | ACS Violation Status (N/A) |
| 20 | RW1CS | 0 | Unsupported Request Error Status |
| 19 | RW1CS | 0 | ECRC Error Status |
| 18 | RW1CS | 0 | Malformed TLP Status |
| 17 | RW1CS | 0 | Receiver Overflow Status |
| 16 | RW1CS | 0 | Unexpected Completion Status |
| 15 | RW1CS | 0 | Completer Abort Status |
| 14 | RW1CS | 0 | Completion Timeout Status |
| 13 | RW1CS | 0 | Flow Control Protocol Error Status |
| 12 | RW1CS | 0 | Poisoned TLP Status |

IF THERE IS ANY OTHER OPERATION TO IMPLEMENT IN ADDITION TO SPECIFICATION IN THE DATASHEET OR JEDEC STANDARD, PLEASE CONTACT EACH BRANCH OFFICE OR HEADQUARTERS OF SAMSUNG ELECTRONICS.

| | | | |
|------|-----------|---|----------------------------------|
| 11:6 | RsvdZ | 0 | Reserved |
| 5 | RW1CS | 0 | Surprise Down Error Status (N/A) |
| 4 | RW1CS | 0 | Data Link Protocol Error Status |
| 3:1 | RsvdZ | 0 | Reserved |
| 0 | Undefined | 0 | Undefined |

[Table 80] AER Uncorrectable Error Mask Register

| Bits | Type | Default Value | Description |
|-------|-----------|---------------|--|
| 31:27 | RsvdZ | 0 | Reserved |
| 26 | RWS | 0 | Poisoned TLP Egress Blocked Mask (N/A) |
| 25 | RWS | 0 | TLP Prefix Blocked Error Mask (N/A) |
| 24 | RWS | 0 | Atomic Op Egress Blocked Mask (N/A) |
| 23 | RWS | 0 | Uncorrectable Internal Error Mask |
| 22 | RWS | 1 | Uncorrectable Internal Error Mask |
| 21 | RWS | 0 | ACS Violation Mask (N/A) |
| 20 | RWS | 0 | Unsupported Request Error Mask |
| 19 | RWS | 0 | ECRC Error Mask |
| 18 | RWS | 0 | Malformed TLP Mask |
| 17 | RWS | 0 | Receiver Overflow Mask |
| 16 | RWS | 0 | Unexpected Completion Mask |
| 15 | RWS | 0 | Completer Abort Mask |
| 14 | RWS | 0 | Completion Timeout Mask |
| 13 | RWS | 0 | Flow Control Protocol Error Mask |
| 12 | RWS | 0 | Poisoned TLP Mask |
| 11:6 | RsvdZ | 0 | Reserved |
| 5 | RWS | 0 | Surprise Down Error Mask (N/A) |
| 4 | RWS | 0 | Data Link Protocol Error Mask |
| 3:1 | RsvdZ | 0 | Reserved |
| 0 | Undefined | 0 | Undefined |

[Table 81] AER Uncorrectable Error Severity Register

| Bits | Type | Default Value | Description |
|-------|-------|---------------|--|
| 31:27 | RsvdP | 0 | Reserved |
| 26 | RWS | 0 | Poisoned TLP Egress Blocked Severity (N/A) |
| 25 | RWS | 0 | TLP Prefix Blocked Error Severity (N/A) |
| 24 | RWS | 0 | Atomic Op Egress Blocked Severity (N/A) |
| 23 | RWS | 0 | MC Blocked TLP Severity (N/A) |
| 22 | RWS | 1 | Uncorrectable Internal Error Severity |
| 21 | RWS | 0 | ACS Violation Severity (N/A) |
| 20 | RWS | 0 | Unsupported Request Error Severity |
| 19 | RWS | 0 | ECRC Error Severity |
| 18 | RWS | 1 | Malformed TLP Severity |
| 17 | RWS | 1 | Receiver Overflow Severity |
| 16 | RWS | 0 | Unexpected Completion Severity |
| 15 | RWS | 0 | Completer Abort Severity |
| 14 | RWS | 0 | Completion Timeout Severity |
| 13 | RWS | 1 | Flow Control Protocol Error Severity |

IF THERE IS ANY OTHER OPERATION TO IMPLEMENT IN ADDITION TO SPECIFICATION IN THE DATASHEET OR JEDEC STANDARD, PLEASE CONTACT EACH BRANCH OFFICE OR HEADQUARTERS OF SAMSUNG ELECTRONICS.

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| 12 | RWS | 0 | Poisoned TLP Severity |
| 11:6 | RsvdP | 0 | Reserved |
| 5 | RWS | 1 | Surprise Down Error Severity (N/A) |
| 4 | RWS | 1 | Data Link Protocol Error Severity |
| 3:1 | RsvdP | 0 | Reserved |
| 0 | Undefined | 0 | Undefined |

[Table 82] AER Correctable Error Status Register

| Bits | Type | Default Value | Description |
|-------|-------|---------------|---------------------------------|
| 31:16 | RsvdZ | 0 | Reserved |
| 15 | RW1CS | 0 | Header Log Overflow Status |
| 14 | RW1CS | 0 | Corrected Internal Error Status |
| 13 | RW1CS | 0 | Advisory Non-Fatal Error Status |
| 12 | RW1CS | 0 | Replay Timer Timeout Status |
| 11:9 | RsvdZ | 0 | Reserved |
| 8 | RW1CS | 0 | Replay Number Rollover Status |
| 7 | RW1CS | 0 | Bad DLLP Status |
| 6 | RW1CS | 0 | Bad TLP Status |
| 5:1 | RsvdZ | 0 | Reserved |
| 0 | RW1CS | 0 | Received Error Status |

[Table 83] AER Correctable Error Mask Register

| Bits | Type | Default Value | Description |
|-------|-------|---------------|-------------------------------|
| 31:16 | RsvdP | 0 | Reserved |
| 15 | RWS | 1 | Header Log Overflow Mask |
| 14 | RWS | 1 | Corrected Internal Error Mask |
| 13 | RWS | 1 | Advisory Non-Fatal Error Mask |
| 12 | RWS | 0 | Replay Timer Timeout Mask |
| 11:9 | RsvdP | 0 | Reserved |
| 8 | RWS | 0 | Replay Number Rollover Mask |
| 7 | RWS | 0 | Bad DLLP Mask |
| 6 | RWS | 0 | Bad TLP Mask |
| 5:1 | RsvdP | 0 | Reserved |
| 0 | RWS | 0 | Received Error Mask |

[Table 84] AER Capabilities and Control Register

| Bits | Type | Default Value | Description |
|-------|-------|---------------|--|
| 31:13 | RsvdP | 0 | Reserved |
| 12 | RO | 0 | Completion Timeout Prefix / Header Log Capable (N/A) |
| 11 | ROS | 0 | TLP Prefix Log Present (N/A) |
| 10 | RWS | 0 | Multiple Header Recording Enable |
| 9 | RO | 1 | Multiple Header Recording Capable |
| 8 | RWS | 0 | ECRC Check Enable |
| 7 | RO | 1 | ECRC Check Capable |
| 6 | RWS | 0 | ECRC Generation Enable |
| 5 | RO | 1 | ECRC Generation Capable |
| 4:0 | ROS | 0 | First Error Pointer |

IF THERE IS ANY OTHER OPERATION TO IMPLEMENT IN ADDITION TO SPECIFICATION IN THE DATASHEET OR JEDEC STANDARD, PLEASE CONTACT EACH BRANCH OFFICE OR HEADQUARTERS OF SAMSUNG ELECTRONICS.

[Table 85] AER Header Log Register

| Bits | Type | Default Value | Description |
|---------|------|---------------|----------------|
| 127:120 | ROS | 0 | Header Byte 0 |
| 119:112 | ROS | 0 | Header Byte 1 |
| 111:104 | ROS | 0 | Header Byte 2 |
| 103:96 | ROS | 0 | Header Byte 3 |
| 95:88 | ROS | 0 | Header Byte 4 |
| 87:80 | ROS | 0 | Header Byte 5 |
| 79:72 | ROS | 0 | Header Byte 6 |
| 71:64 | ROS | 0 | Header Byte 7 |
| 63:56 | ROS | 0 | Header Byte 8 |
| 55:48 | ROS | 0 | Header Byte 9 |
| 47:40 | ROS | 0 | Header Byte 10 |
| 39:32 | ROS | 0 | Header Byte 11 |
| 31:24 | ROS | 0 | Header Byte 12 |
| 23:16 | ROS | 0 | Header Byte 13 |
| 15:8 | ROS | 0 | Header Byte 14 |
| 7:0 | ROS | 0 | Header Byte 15 |

5.1.4.2 Secondary PCI Express Capability

[Table 86] Secondary PCI Express Capability Summary

| Start Address | End Address | Symbol | Description |
|---------------|-------------|----------|---|
| 178h | 17Bh | SPE_ID | Secondary PCI Express Capability Header |
| 17Ch | 17Fh | SPE_LC# | PCI Express Link Control 3 |
| 180h | 183h | SPE_LE | PCI Express Lane Error Status |
| 184h | 185h | SPE_L0EC | PCI Express Lane 0 Equalization Control |
| 186h | 187h | SPE_L1EC | PCI Express Lane 1 Equalization Control |
| 188h | 189h | SPE_L2EC | PCI Express Lane 2 Equalization Control |
| 18Ah | 18Bh | SPE_L3EC | PCI Express Lane 3 Equalization Control |

[Table 87] Secondary PCI Express Capability ID Register

| Bits | Type | Default Value | Description |
|-------|------|---------------|---|
| 31:20 | RO | 000h | Next Capability Offset |
| 19:16 | RO | 1h | Capability Version |
| 15:0 | RO | 19h | Capability ID (Secondary PCI Express Extended capability) |

[Table 88] PCI Express Link Control 3 Register

| Bits | Type | Default Value | Description |
|-------|-------|---------------|--|
| 31:16 | RsvdP | 0 | Reserved |
| 15:9 | RW | 0 | Enable Lower SKP OS Generation Vector (N/A) |
| 8:2 | RsvdP | 0 | RsvdP |
| 1 | RW | 0 | Link Equalization Request Interrupt Enable (N/A) |
| 0 | RW | 0 | Perform Equalization (N/A) |

[Table 89] PCI Express Lane Error Status Register

| Bits | Type | Default Value | Description |
|------|-------|---------------|------------------------|
| 31:4 | RsvdP | 0 | Reserved |
| 3:0 | RW1CS | 0 | Lane Error Status Bits |

[Table 90] PCI Express Lane 0 Equalization Register

| Bits | Type | Default Value | Description |
|-------|--------------|---------------|---|
| 15 | RsvdP | 0 | Reserved |
| 14:12 | Hwlnit/RO | 7h | Upstream Port 8.0T/s Receiver Preset Hint |
| 11:8 | Hwlnit/RO | Fh | Upstream Port 8.0T/s Transmitter Preset |
| 7 | RsvdZ | 0 | Reserved |
| 6:4 | Hwlnit/RsvdP | 0 | Downstream Port 8.0T/s Receiver Preset Hint (N/A) |
| 3:0 | Hwlnit/RsvdP | 0 | Downstream Port 8.0T/s Transmitter Preset (N/A) |

[Table 91] PCI Express Lane 1 Equalization Register

| Bits | Type | Default Value | Description |
|-------|--------------|---------------|---|
| 15 | RsvdP | 0 | Reserved |
| 14:12 | Hwlnit/RO | 7h | Upstream Port 8.0T/s Receiver Preset Hint |
| 11:8 | Hwlnit/RO | Fh | Upstream Port 8.0T/s Transmitter Preset |
| 7 | RsvdZ | 0 | Reserved |
| 6:4 | Hwlnit/RsvdP | 0 | Downstream Port 8.0T/s Receiver Preset Hint (N/A) |
| 3:0 | Hwlnit/RsvdP | 0 | Downstream Port 8.0T/s Transmitter Preset (N/A) |

[Table 92] PCI Express Lane 2 Equalization Register

| Bits | Type | Default Value | Description |
|-------|--------------|---------------|---|
| 15 | RsvdP | 0 | Reserved |
| 14:12 | Hwlnit/RO | 7h | Upstream Port 8.0T/s Receiver Preset Hint |
| 11:8 | Hwlnit/RO | Fh | Upstream Port 8.0T/s Transmitter Preset |
| 7 | RsvdZ | 0 | Reserved |
| 6:4 | Hwlnit/RsvdP | 0 | Downstream Port 8.0T/s Receiver Preset Hint (N/A) |
| 3:0 | Hwlnit/RsvdP | 0 | Downstream Port 8.0T/s Transmitter Preset (N/A) |

[Table 93] PCI Express Lane 3 Equalization Register

| Bits | Type | Default Value | Description |
|-------|--------------|---------------|---|
| 15 | RsvdP | 0 | Reserved |
| 14:12 | Hwlnit/RO | 7h | Upstream Port 8.0T/s Receiver Preset Hint |
| 11:8 | Hwlnit/RO | Fh | Upstream Port 8.0T/s Transmitter Preset |
| 7 | RsvdZ | 0 | Reserved |
| 6:4 | Hwlnit/RsvdP | 0 | Downstream Port 8.0T/s Receiver Preset Hint (N/A) |
| 3:0 | Hwlnit/RsvdP | 0 | Downstream Port 8.0T/s Transmitter Preset (N/A) |

5.2 NVM Express Registers

5.2.1 Register Summary

[Table 94] Register Summary

| Start Address | End Address | Name | Type |
|---------------------------------------|---------------------------------------|----------|--|
| 00h | 07h | CAP | Controller Capabilities |
| 08h | 0Bh | VS | Version |
| 0Ch | 0Fh | INTMS | Interrupt Mask Set |
| 10h | 13h | INTMC | Interrupt Mask Clear |
| 14h | 17h | CC | Controller Configuration |
| 18h | 1Bh | Reserved | Reserved |
| 1Ch | 1Fh | CSTS | Controller Status |
| 20h | 23h | Reserved | Reserved |
| 24h | 27h | AQA | Admin Queue Attributes |
| 28h | 2Fh | ASQ | Admin Submission Queue Base Address |
| 30h | 37h | ACQ | Admin Completion Queue Base Address |
| 38h | EFFh | Reserved | Reserved |
| F00h | FFFh | Reserved | Command Set Specific |
| 1000h | 1003h | SQ0TDBL | Submission Queue 0 Tail Doorbell (Admin) |
| 1000h + (1 * (4 << CAP.DSTRD)) | 1003h + (1 * (4 << CAP.DSTRD)) | CQ0HDBL | Completion Queue 0 Head Doorbell (Admin) |
| ... | | | |
| 1000h + (2y * (4 << CAP.DSTRD)) | 1003h + (2y * (4 << CAP.DSTRD)) | SQyTDBL | Submission Queue y Tail Doorbell |
| 1000h + ((2y + 1) * (4 << CAP.DSTRD)) | 1003h + ((2y + 1) * (4 << CAP.DSTRD)) | CQyHDBL | Completion Queue y Head Doorbell |

5.2.2 Controller Registers

[Table 95] Controller Capabilities

| Bits | Type | Name | Default Value | Description |
|-------|------|--------|---------------|---|
| 63:56 | RO | - | 0h | Reserved |
| 55:52 | RO | MPSMAX | 0Fh | Memory Page Size Maximum ((2 ^ (12 + MPSMAX)). |
| 51:48 | RO | MPSMIN | 0 | Memory Page Size Minimum (2 ^ (12 + MPSMIN)). |
| 47:41 | RO | - | 0 | Reserved |
| 40:37 | RO | CSS | 1h | Command Sets Supported 1h: NVM command set |
| 36 | RO | NSSRS | 1 | NVM Subsystem Reset Supported (NSSRS) |
| 35:32 | RO | DSTRD | 0 | Doorbell Stride 0: Stride of 4 bytes |
| 31:24 | RO | TO | 78h | Timeout (This field is in 500 millisecond units) |
| 23:19 | RO | - | 0 | Reserved |
| 18:17 | RO | AMS | 1 | Arbitration Mechanism Supported |
| 16 | RO | CQR | 1 | Contiguous Queues Required |
| 15:0 | RO | MQES | 3FFh | Maximum Queue Entries Supported |

[Table 96] Version

| Bits | Type | Name | Default Value | Description |
|-------|------|------|---------------|----------------------|
| 31:16 | RO | MJR | 1h | Major Version Number |
| 15:0 | RO | MNR | 200h | Minor Version Number |

NOTE:

The SZ1735 supports NVM Express version 1.1c.

[Table 97] Interrupt Mask Set

| Bits | Type | Name | Default Value | Description |
|-------|------|------|---------------|---------------------------|
| 31:00 | RW1S | IVMS | 1h | Interrupt Vector Mask Set |

[Table 98] Interrupt Mask Clear

| Bits | Type | Name | Default Value | Description |
|-------|------|------|---------------|-----------------------------|
| 31:00 | RW1C | IVMC | 1h | Interrupt Vector Mask Clear |

[Table 99] Controller Configuration

| Bits | Type | Name | Default Value | Description |
|-------|------|--------|---------------|--|
| 31:24 | RO | - | 0 | Reserved |
| 23:20 | RW | IOCQES | 4 | I/O Completion Queue Entry Size (Configured as a power of 2) (Should be set to 4 for a 16 byte entry size) |
| 19:16 | RW | IOSQES | 6 | I/O Submission Queue Entry Size (Configured as a power of 2) (Should be set to 6 for a 64 byte entry size) |
| 15:14 | RW | SHN | 0 | Shutdown Notification 0h: No notification 1h: Normal shutdown notification 2h: Abrupt shutdown notification 3h: Reserved CSTS.SHST indicates shutdown status. |
| 13:11 | RW | AMS | 0 | Arbitration Mechanism Selected 0h: Round Robin No other values supported. |
| 10:7 | RW | MPS | 0 | Memory Page Size MPS is 2^(12+MPS) Shall be within CAP.MPSMAX and CAP.MPSMIN ranges. |
| 6:4 | RW | CSS | 0 | Command Set Selected 0h: NVM Command Set No other values supported |
| 3:1 | RO | - | 0 | Reserved |
| 0 | RW | EN | 0 | Enable When set to 1, controller shall process commands. When cleared to 0, controller shall not process commands. This field is subject to CSTS.RDY and CAP.TO restrictions. |

[Table 100] Controller Status

| Bits | Type | Name | Default Value | Description |
|------|------|-------|---------------|---|
| 31:6 | RO | - | 0 | Reserved |
| 5 | RO | PP | 0 | Processing Paused |
| 4 | RW1C | NSSRO | 0 | NVM Subsystem Reset Occurred |
| 3:2 | RO | SHST | 0 | Shutdown Status 0h: Normal operation, no shutdown requested 1h: Shutdown processing occurring 2h: Shutdown processing complete 3h: Reserved |
| 1 | RO | CFS | 0 | Controller Fatal Status |
| 0 | RO | RDY | 0 | 1h: Controller ready to process commands 0h: Controller shall not process commands. |

[Table 101] Admin Queue Attributes

| Bits | Type | Name | Default Value | Description |
|-------|------|------|---------------|---|
| 31:28 | RO | - | 0 | Reserved |
| 27:16 | RW | ACQS | 0 | Admin Completion Queue Size Max: 4096 (Value of 4095h - 0's based value) |
| 15:12 | RO | - | 0 | Reserved |
| 11:0 | RW | ASQS | 0 | Admin Submission Queue Size Max: 4096 (Value of 4095h - 0's based value) |

[Table 102] Admin Submission Queue Base Address

| Bits | Type | Name | Default Value | Description |
|-------|------|------|---------------|-------------------------------------|
| 63:12 | RW | ASQB | 0 | Admin Submission Queue Base Address |
| 11:0 | RO | - | 0 | Reserved |

[Table 103] Admin Completion Queue Base Address

| Bits | Type | Name | Default Value | Description |
|-------|------|------|---------------|-------------------------------------|
| 63:12 | RW | ACQB | 0 | Admin Completion Queue Base Address |
| 11:0 | RO | - | 0 | Reserved |

[Table 104] Submission Queue Tail y Doorbell

| Bits | Type | Name | Default Value | Description |
|-------|------|------|---------------|-----------------------|
| 31:16 | RO | | 0 | Reserved |
| 15:0 | RW | SQT | 0 | Submission Queue Tail |

[Table 105] Completion Queue Head y Doorbell

| Bits | Type | Name | Default Value | Description |
|-------|------|------|---------------|-----------------------|
| 31:16 | RO | | 0 | Reserved |
| 15:0 | RW | CQH | 0 | Completion Queue Head |

6.0 SUPPORTED COMMAND SET.

6.1 Admin Command Set

[Table 106] Opcode for Admin Commands

| Opcode (Hex) | Command Name |
|--------------|--|
| 00h | Delete I/O Submission Queue |
| 01h | Create I/O Submission Queue |
| 02h | Get Log Page - Error Information (01h) - SMART/Health Information (02h) - Firmware Slot Information (03h, M) |
| 04h | Delete I/O Completion Queue |
| 05h | Create I/O Completion Queue |
| 06h | Identify |
| 08h | Abort |
| 09h | Set Feature - Arbitration (01h) - Power Management (02h) - LBA Range Type (03h) - Temperature Threshold (04h) - Error Recovery (05h) - Number of Queues (07h) - Interrupt Coalescing (08h) - Interrupt Vector Configuration (09h) - Write Atomicity (0Ah) - Asynchronous Event Configuration (0Bh) - Software Progress Marker (80h) |
| 0Ah | Get Feature - Arbitration (01h) - LBA Range Type (03h) - Temperature Threshold (04h) - Error Recovery (05h) - Number of Queues (07h) - Interrupt Coalescing (08h) - Interrupt Vector Configuration (09h) - Write Atomicity (0Ah) - Asynchronous Event Configuration (0Bh) - Software Progress Marker (80h) |
| 0Ch | Asynchronous Event Request |
| 10h | Firmware Activate |
| 11h | Firmware Image Download |
| 80h | Format NVM |
| 81h – BFh | I/O Command Set Specific |

6.1.1 Identify Command

The Identify Command returns the data described below.

[Table 107] Identify Controller Data Structure

| Bytes | O/M | Default Value | Description |
|---------|-----|---|---|
| 1:0 | M | 144Dh | PCI Vendor ID |
| 3:2 | M | 108Eh | PCI Subsystem Vendor ID |
| 23:4 | M | SXXXXXXXXXXXXXX | Serial Number (ASCII), X: Variables |
| 63:24 | M | 800GB:MZWJ800HMGQ-00007 1.6TB:MZWJ1T6HMGG-00007 3.2TB:MZWJ3T2HMHN-00007 | Model Number (ASCII) |
| 71:64 | M | ##### | Firmware Revision, #: Variables |
| 72 | M | 8h | Recommended Arbitration Burst |
| 75:73 | M | 002538h | IEEE OUI Byte 73 - 38h Byte 74 - 25h Byte 75 - 0h |
| 76 | O | 3h | Multi-Interface Capabilities 0h: Not supported (single port) 1h: Supported (dual port – future value) |
| 77 | M | 5h | Maximum Data Transfer Size 0h: No restrictions |
| 79:78 | M | 0h | Controller ID (CNTLID) |
| 83:80 | M | 10200h | Version (VER) |
| 87:84 | M | 0h | RTD3 Resume Latency (RTD3R) |
| 91:88 | M | 0h | RTD3 Entry Latency (RTD3E) |
| 95:92 | M | 0h | Optional Asynchronous Event Supported (OAES) |
| 239:96 | | - | Reserved |
| 255:240 | | Refer to the NVMe Management Interface Specification for definition. | |
| 257:256 | M | 07h | Optional Admin Command Support Bits 15:3 - Reserved Bit 3: Namespace Management and Namespace Attachment command Supported Bit 2: 1h – Firmware Activate/Download Supported Bit 1: 1h Format NVM Supported Bit 0: 0 Security Send and Security Receive Not Supported (TBD) |
| 258 | M | 7h | Abort Command Limit (Maximum number of concurrently outstanding Abort commands) (0's based value) |
| 259 | M | Fh | Asynchronous Event Request Limit (Maximum number of concurrently outstanding Asynchronous Event Request commands) (0's based value) |
| 260 | M | 2h | Firmware Updates Bits 7:4 – Reserved Bits 3:1 – Number of firmware slots Bit 0 – 1h Slot 1 is read only |
| 261 | M | 0h | Log Page Attributes Bits 7:1 – Reserved Bit 0: 0h SMART data is global for all Namespaces |
| 262 | M | FFh | Error Log Page Entries (Number of Error Information log entries stored by controller) (0's based value) |
| 263 | M | 0h | Number of Power States Support (0's based value) |
| 264 | M | 1h | Admin Vendor Specific Command Configuration Bits 7:1 – reserved Bit 0 – Indicates Admin Vendor Specific Commands use the format defined in NVM Express 1.1b Figure 8. |

IF THERE IS ANY OTHER OPERATION TO IMPLEMENT IN ADDITION TO SPECIFICATION IN THE DATASHEET OR JEDEC STANDARD, PLEASE CONTACT EACH BRANCH OFFICE OR HEADQUARTERS OF SAMSUNG ELECTRONICS.

| | | | |
|----------------------------|---|--|---|
| 265 | O | 0h | Autonomous Power State Transition Attributes (APSTA) |
| 267:266 | M | 160h | Warning Composite Temperature Threshold (WCTEMP) |
| 269:268 | M | 167h | Critical Composite Temperature Threshold (CCTEMP) |
| 271:270 | O | 78h | Maximum Time for Firmware Activation (MTFA) |
| 275:272 | O | 0h | Host Memory Buffer Preferred Size (HMPRE): |
| 279:276 | O | 0h | Host Memory Buffer Minimum Size (HMMIN): |
| 295:280 | O | 800GB:BA4D9D6000 1.6TB:1749A956000 3.2TB:2E934856000 | Total NVM Capacity (TNVMCAP): |
| 311:296 | O | 0h | Unallocated NVM Capacity (UNVMCAP): |
| 315:312 | O | 0h | Replay Protected Memory Block Support (RPMBS): |
| 511:316 | - | - | Reserved |
| 512 | M | 66h | Submission Queue Entry Size Bits 7:4 – 6h Max SQES (64 bytes) Bits 3:0 – 6h Required SQES (64 bytes) |
| 513 | M | 44h | Completion Queue Entry Size Bits 7:4 – 4h Max SQES (16 bytes) Bits 3:0 – 4h Required SQES (16 bytes) |
| 515:514 | - | - | Reserved |
| 519:516 | M | 1h | Number of Namespaces |
| 521:520 | M | 4h | Optional NVM Command Support Bits 51:3 – Reserved Bit 2 – 1h Dataset Management Supported Bit 1 – 0h Write Uncorrectable Supported Bit 0 – 0h Compare Not Supported |
| 523:522 | M | 0h | Fused Operation Support Bits 15:1 – Reserved Bit 0 – 0h Compare/Write Fused Operation Not Supported |
| 524 | M | 6h | Format NVM Attributes Bits 7:3 – Reserved Bit 2 – 1h Cryptographic Erase Bit 1 – 1h Secure Erase is applied for All Namespaces Bit 0 – 0h Format Per Namespace |
| 525 | M | 0h | Volatile Write Cache 0h – No VWC present |
| 527:526 | M | FFFFh | Atomic Write Unit Normal All commands atomic |
| 529:528 | M | 0h | Atomic Write Unit Power Fail (0's based value) |
| 530 | M | 1h | NVM Vendor Specific Command Configuration Bits 7:1 – reserved Bit 0 – Indicates NVM Vendor Specific Commands use the format defined in NVM Express 1.2 Figure 8. |
| 531 | M | - | Reserved |
| 533:532 | O | 0h | Atomic Compare & Write Unit (ACWU) |
| 535:534 | M | - | Reserved |
| 539:536 | O | 0h | SGL Support (SGLS) |
| 703:540 | M | - | Reserved |
| I/O Command Set Attributes | | | |
| 2047:704 | - | - | Reserved |
| Power State Descriptors | | | |
| 2079:2048 | M | - | Power State 0 Descriptor |
| 2111:2080 | O | - | Power State 1 Descriptor (N/A) |
| ... | - | - | |
| 3071:3040 | O | - | Power State 31 Descriptor (N/A) |
| 4095:3072 | - | 0h | Samsung Reserved |

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[Table 108] Identify Power State Descriptor Data Structure

| Bytes | Default Value | Description |
|---------|---------------|---------------------------|
| 255:125 | 0 | Reserved |
| 124:120 | 0 | Relative Write Latency |
| 119:117 | 0 | Reserved |
| 116:112 | 0 | Relative Write Throughput |
| 111:109 | 0 | Reserved |
| 108:104 | 0 | Relative Read Latency |
| 103:101 | 0 | Reserved |
| 100:96 | 0 | Relative Read Throughput |
| 95:64 | 100 | Exit Latency (100us) |
| 63:32 | 100 | Entry Latency (100us) |
| 31:16 | 0 | Reserved |
| 15:00 | 09C4h | Maximum Power (25W) |

[Table 109] Identify Namespace Data Structure

| Bytes | O/M | Default Value | Description |
|-------|-----|---|---|
| 7:0 | M | 800GB:5D26CEB0 (512B), BA4D9D6 (4096) 1.6TB:BA4D4AB0 (512B), 1749A956 (4096) 3.2TB:1749A42B0 (512B), 2E934856 (4096) | Namespace Size |
| 15:8 | M | 800GB:5D26CEB0 (512B), BA4D9D6 (4096) 1.6TB:BA4D4AB0 (512B), 1749A956 (4096) 3.2TB:1749A42B0 (512B), 2E934856 (4096) | Namespace Capacity |
| 23:16 | M | 800GB:5D26CEB0 (512B), BA4D9D6 (4096) 1.6TB:BA4D4AB0 (512B), 1749A956 (4096) 3.2TB:1749A42B0 (512B), 2E934856 (4096) | Namespace Utilization |
| 24 | M | 0h | Namespace Features Bits 7:1 Reserved Bit 0: Thin provisioning not supported |
| 25 | M | 3h | Number of LBA Formats |
| 26 | M | 10h | Formatted LBA Size Bits 7:5 – Reserved Bit 4: Metadata interleaved or separate (based on LBA format) Bit 3:0 – Indicates LBA format |
| 27 | M | 3h | Metadata Capabilities Bits 7:2 – Reserved Bit 1 – Supports Metadata as separate buffer Bit 0 – Supports Metadata as extended LBA |
| 28 | M | 1Fh | End-to-end Data Protection Capabilities Bits 7:5 – Reserved Bit 4 – Supports protection information as last 8 bytes of Metadata Bit 3 – Supports protection information as first 8 bytes of Metadata Bit 2 – Supports Type 3 protection information Bit 1 – Supports Type 2 protection information Bit 0 – Supports Type 1 protection information |

| | | | |
|-----------------|---|--|--|
| 29 | M | 0h | End-to-End Data Protection Type Settings Bits 7:4 – Reserved Bit 3 – 1: Protection information transferred as first 8 bytes of Metadata Bit 3 – 0: Protection information transferred as last 8 bytes of Metadata Bit 2:0 – 000b: Protection information disabled Bit 2:0 – 1h: Protection type 1 enabled Bit 2:0 – 2h: Protection type 2 enabled Bit 2:0 – 3h: Protection type 3 enabled |
| 30 | | 0h | Namespace Multi-path I/O and Namespace Sharing Capabilities (NMIC): |
| 31 | | 0h | Reservation Capabilities (RESCAP): |
| 32 | | 0h | Format Progress Indicator (FPI) |
| 33 | | - | Reserved |
| 35:34 | O | 0h | Namespace Atomic Write Unit Normal (NAWUN) |
| 37:36 | O | 0h | Namespace Atomic Write Unit Power Fail (NAWUPF) |
| 39:38 | O | 0h | Namespace Atomic Compare & Write Unit (NACWU) |
| 41:40 | O | 0h | Namespace Atomic Boundary Size Normal (NABSN) |
| 43:42 | O | 0h | Namespace Atomic Boundary Offset (NABO) |
| 45:44 | O | 0h | Namespace Atomic Boundary Size Power Fail (NABSPF) |
| 47:46 | - | - | Reserved |
| 63:48 | | 800GB:BA4D9D6000 1.6TB:1749A956000 3.2TB:2E934856000 | NVM Capacity (NVMCAP) |
| 103:64 | - | - | Reserved |
| 119:104 | O | 0h | Namespace Globally Unique Identifier (NGUID) |
| 127:120 | O | TBD | IEEE Extended Unique Identifier(EUI64) |
| 131:128 | M | 1090000h | LBA Format 0 Support |
| 135:132 | O | 3090008h | LBA Format 1 Support |
| 139:136 | O | C0000h | LBA Format 2 Support |
| 143:140 | O | 20C0008h | LBA Format 3 Support |
| 147:144 | O | - | LBA Format 4 Support (N/A) |
| ... | | | |
| 191:188 | O | - | LBA Format 15 Support (N/A) |
| 383:192 | - | - | Reserved |
| Vendor Specific | | | |
| 4095:384 | - | - | Samsung Reserved |

[Table 110] LBA Format 0 Data Structure

| Bits | Name | Default Value | Description |
|-------|-------|---------------|----------------------|
| 31:26 | | 0h | Reserved |
| 25:24 | RP | 1h | Relative Performance |
| 23:16 | LBADS | 9h | LBA Data Size |
| 15:00 | MS | 0h | Metadata Size |

[Table 111] LBA Format 1 Data Structure

| Bits | Name | Default Value | Description |
|-------|-------|---------------|----------------------|
| 31:26 | | 0h | Reserved |
| 25:24 | RP | 3h | Relative Performance |
| 23:16 | LBADS | 9h | LBA Data Size |
| 15:00 | MS | 8h | Metadata Size |

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[Table 112] LBA Format 2 Data Structure

| Bits | Name | Default Value | Description |
|-------|-------|---------------|----------------------|
| 31:26 | | 0 | Reserved |
| 25:24 | RP | 0h | Relative Performance |
| 23:16 | LBADS | Ch | LBA Data Size |
| 15:00 | MS | 0h | Metadata Size |

[Table 113] LBA Format 3 Data Structure

| Bits | Name | Default Value | Description |
|-------|-------|---------------|--------------------------------------|
| 31:26 | | 0 | Reserved |
| 25:24 | RP | 2h | Relative Performance |
| 23:16 | LBADS | Ch | LBA Data Size (2 ⁿ bytes) |
| 15:00 | MS | 8h | Metadata Size (bytes) |

6.2 NVM Express I/O Command Set

[Table 114] Opcode for NVM Express I/O Commands

| Opcode (Hex) | Command Name |
|--------------|--------------------|
| 00h | Flush |
| 01h | Write |
| 02h | Read |
| 09h | Dataset Management |

NOTE:

1) Deallocate feature in Dataset Management command is only supported in the Samsung SSD SZ1735.

7.0 SFF-8639 SMBus RESOURCES

This section listed data structures and registers accessible through SMBus interface.

Vital Product Data (VPD) is stored in SM-Bus slave address of 0xA6 (bits 7-1 correspond to 1010_011 on the SM-Bus). Temperature sensor is stored in SM-Bus slave address of 0xD4 (bits 7-1 correspond to 1101_010).

7.1 Vital Product Data (VPD) Structure

VPD listed device specific information for Enterprise PCIe SSD discovery and power allocation.

| Bytes | Name | Default Value | Description |
|---------|----------------------------|--|---|
| 02:00 | Class Code | 010802h | Device Type & Programming Interface |
| 04:03 | ID | 144Dh | PCI-SIG Vendor ID |
| 24:05 | ID | SXXXNXXXXXXXXXX | Serial Number (Vendor Unique, ASCII String), X: Variables |
| 64:25 | ID | 800GB:MZWJJ800HMGQ-00007 1.6TB:MZWJJ1T6HMGG-00007 3.2TB:MZWJJ3T2HMHN-00007 | Model Number (ASCII String) |
| 65:65 | PCIe Port 0 Capabilities | 03h | Maximum Link Speed (PCIe Gen3) |
| 66:66 | PCIe Port 0 Capabilities | 04h | Maximum Link Width (x8) |
| 67:67 | PCIe Port 1 Capabilities | 03h | Maximum Link Speed (PCIe Gen3) |
| 68:68 | PCIe Port 1 Capabilities | 04h | Maximum Link Width (x8) |
| 69:69 | Initial Power Requirements | 07h | 12V Power rail initial power requirement (7 W) |
| 71:70 | Initial Power Requirements | 0h | Reserved |
| 72:72 | Max power Requirement | 14h | 12V Power rail maximum power requirement (20W) |
| 74:73 | Max power Requirement | 0h | Reserved |
| 76:75 | Cap List Pointer | 0050h | Start Cap Address Pointer (0x50) |
| 79:77 | - | 0h | - |
| 81:80 | - | 00A2h | VU Cap ID |
| 83:82 | - | 0070h | Next Cap Address (0x0070 VU Samsung Specific) |
| 84:84 | Sensor Type | 02h | - |
| 85:85 | Sensor Address | 36h | - |
| 87:86 | - | 0h | Reserved |
| 88:88 | Warning Thresh - LSB | E0h | - |
| 89:89 | Warning Thresh - MSB | 04h | - |
| 90:90 | OverTemp Thresh - LSB | 50h | - |
| 91:91 | OverTemp Thresh - MSB | 05h | - |
| 111:92 | - | FFh | Reserved |
| 113:112 | - | 00A0h | Dual Port Mode Capability |
| 115:114 | - | 0074h | Next Cap Address (0x0074 Dual Active/Passive Capability) |
| 117:116 | - | 00A3h | Dual Active/Passive Capability |
| 119:118 | - | 0000h | Next Cap Address (NULL) |
| 120:120 | - | 03h | Dual Port Vector (Dual Port Passive) |
| 255:121 | - | FFh | Reserved |

NOTE: TSE2004av temperature encoding:

| B15/B07 | B14/B06 | B13/B05 | B12/B04 | B11/B03 | B10/B02 | B09/B01 | B08/B00 |
|---------|---------|---------|---------|---------|---------|---------|---------|
| N/A | N/A | N/A | Sign | 128 | 64 | 32 | 16 |
| 8 | 4 | 2 | 1 | N/A | N/A | N/A | N/A |

The 16-bit value is 2s complement representation of a temperature with the Bit 4 equal to the minimum granularity of 1 °C. Bit 12 is the sign bit.

For example:

1. a value of 0190h represents 25 °C,
2. a value of 07C0 h represents 124 °C, and
3. a value of 1E80 h represents -24 °C

By choosing the starting of the lowest bit the resolution of the temperature sensor can be defined. For SMBus temperature capability support PM1725's temperature sensor is at resolution of 1°C (8-bit)

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7.2 Temperature Sensor Register Summary

| Offset | Type | Name | Description | Default |
|--------|------|-----------------|--|---------|
| 00 | RO | Capabilities | Indicates the functions and capabilities | 0006h |
| 01 | RW | Configuration | Temperature sensor control | 0000h |
| 02 | RW | High Limit | Temperature High Limit | 0x04C0 |
| 03 | RW | Low Limit | Temperature Low Limit | 0 |
| 04 | RW | TCRIT Limit | Critical Temperature | 0x0530 |
| 05 | RO | Ambient Temp | Current Ambient Temperature | N/A |
| 06 | RO | Manufacture ID | PCI-SIG Manufacture ID | 144Dh |
| 07 | RO | Device/Revision | Device ID and Revision number | A821h |

7.2.1 Capabilities Register

| Bits | Type | Default Value | Description |
|-------|------|---------------|--|
| 15:07 | RO | 0 | Reserved |
| 6 | RO | 0 | Bus timeout period for thermal sensor access during normal operation. 0 = timeout is supported in the range of 10 to 60 ms 1 = timeout is supported in the range of 25ms to 35 ms (SMBus Compatible) |
| 5 | RO | 0 | Reserved |
| 04:03 | RO | 0 | Reserved |
| 2 | RO | 1 | Range Width: 0 = The temperature monitor clamps values lower than 0 °C 1 = The temperature monitor can read temperatures below 0 °C and sets the sign bit appropriately) |
| 1 | RO | 1 | Accuracy: 0 = Accuracy ±2 °C over the active range and ±3 °C over the monitoring range (C-grade). 1 = High accuracy ±1 °C over the active range and ±2 °C over the monitoring range (B-grade) |
| 0 | RO | 0 | Event: 0 = The device does not support interrupt capabilities. 1 = The device supports interrupt capabilities. |

7.2.2 Configuration Register

| Bits | Type | Default Value | Description |
|-------|------|---------------|---|
| 15:11 | RW | 0 | Reserved |
| 10:09 | RW | 0 | Hysteresis: Control the hysteresis that is applied to all limits 00 = Hysteresis is disabled 01 = Hysteresis is enabled at 2C 10 = Hysteresis is enabled at 3 °C 11 = Hysteresis is enabled at 6 °C |
| 08:00 | RW | 0 | Reserved |

7.2.3 High Limit Register

| Bits | Type | Default Value | Description |
|-------|------|---------------|-----------------------------|
| 15:13 | RW | 0 | Reserved |
| 12 | RW | 0 | Sign bit of the temperature |
| 11 | RW | 0 | 128 degree Celsius |
| 10 | RW | 1 | 64 degree Celsius |
| 09 | RW | 0 | 32 degree Celsius |
| 08 | RW | 0 | 16 degree Celsius |
| 07 | RW | 1 | 8 degree Celsius |
| 06 | RW | 0 | 4 degree Celsius |
| 05 | RW | 1 | 2 degree Celsius |
| 04 | RW | 0 | 1 degree Celsius |
| 03:00 | RW | 0 | Reserved |

7.2.4 Low Limit Register

| Bits | Type | Default Value | Description |
|-------|------|---------------|-----------------------------|
| 15:13 | RW | 0 | Reserved |
| 12 | RW | 0 | Sign bit of the temperature |
| 11 | RW | 0 | 128 degree Celsius |
| 10 | RW | 0 | 64 degree Celsius |
| 09 | RW | 0 | 32 degree Celsius |
| 08 | RW | 0 | 16 degree Celsius |
| 07 | RW | 0 | 8 degree Celsius |
| 06 | RW | 0 | 4 degree Celsius |
| 05 | RW | 0 | 2 degree Celsius |
| 04 | RW | 0 | 1 degree Celsius |
| 03:00 | RW | 0 | Reserved |

7.2.5 Critical Temperature Register

| Bits | Type | Default Value | Description |
|-------|------|---------------|-----------------------------|
| 15:13 | RW | 0 | Reserved |
| 12 | RW | 0 | Sign bit of the temperature |
| 11 | RW | 0 | 128 degree Celsius |
| 10 | RW | 1 | 64 degree Celsius |
| 09 | RW | 0 | 32 degree Celsius |
| 08 | RW | 1 | 16 degree Celsius |
| 07 | RW | 0 | 8 degree Celsius |
| 06 | RW | 0 | 4 degree Celsius |
| 05 | RW | 0 | 2 degree Celsius |
| 04 | RW | 0 | 1 degree Celsius |
| 03:00 | RW | 0 | Reserved |

7.2.6 Ambient Temperature Register

| Bits | Type | Default Value | Description |
|-------|------|---------------|---|
| 15 | RO | 0 | TCRIT Flag: The temperature is above the TCRIT Limit. |
| 14 | RO | 0 | High Flag: The temperature is above the High Limit. |
| 13 | RO | 0 | Low Flag: The temperature is below the Low Limit. |
| 12 | RO | 0 | Sign bit of the temperature |
| 11 | RO | 0 | 128 degree Celsius |
| 10 | RO | 0 | 64 degree Celsius |
| 09 | RO | 0 | 32 degree Celsius |
| 08 | RO | 0 | 16 degree Celsius |
| 07 | RO | 0 | 8 degree Celsius |
| 06 | RO | 0 | 4 degree Celsius |
| 05 | RO | 0 | 2 degree Celsius |
| 04 | RO | 0 | 1 degree Celsius |
| 03:00 | RO | 0 | Reserved |

7.2.7 Manufacture ID Register

| Bits | Type | Default Value | Description |
|------|------|---------------|------------------------|
| 15:0 | RO | 144Dh | PCI-SIG Manufacture ID |

7.2.8 Device/Revision Register

| Bits | Type | Default Value | Description |
|------|------|---------------|-------------------------------|
| 15:0 | RO | 0xA821 | Device ID and Revision Number |

8.0 UEFI EXPANSION ROM

The expansion ROM integrated in Samsung SSD SZ1735 supports booting UEFI operating system installed on the drive, it complies to UEFI standard, which is specified in UEFI v2.5 Specification.

8.1 Basic Information

- IA32/x64 architecture support: x64 only
- Binary executable size < 64KB
- Platform BIOS requirement: EFI Specification Revision 2.31+, EFI Shell Version 1.0
- Number of Admin Submission Queue/Admin Completion Queue entries: 2
- Number of IO Queue entries: 2
- Maximum number of IO queues supported: 2
- Interrupt used: None

8.1.1 General Features

- Supports various operating systems booting in UEFI mode
- Ability to boot from large partition (over 2TB) with GUID Partition Table (GPT)
- Provides drive information via UEFI user interface (HII) in pre-boot environment (such as model number, firmware revision and drive capacity)
- Supports Secure Boot
- UEFI standard APIs supporting followings in pre-boot environment (EFI Shell):
 - . Basic block read/write access (produced API: EfiBlockIoProtocol)
 - . Driver health information (produced API: EfiDriverHealthProtocol)
 - . Drive diagnostic function (produced API: EfiDriverDiagnostics2Protocol)
 - . NVMHCI functions: GetLogPage, Firmware Download/Activate and Format (produced API: EfiFirmwareManagementProtocol and NvmExpressPassThruProtocol)

8.2 Supported Operating Systems

| Index | Operating Systems bootable on SZ1735 drive |
|-------|--|
| 1 | Windows Server 2008 R2 64-bit |
| 2 | Windows Server 2012 64-bit |
| 3 | Windows Server 2012 R2 64-bit |
| 4 | Windows Server 2016 64-bit |
| 5 | RHEL 6.4 (Kernel 2.6.32) |
| 6 | RHEL 6.5 (Kernel 2.6.32) |
| 7 | RHEL 6.6 (Kernel 2.6.32) |
| 8 | RHEL 7 (Kernel 3.10.0) |
| 9 | RHEL 7.1 (Kernel 3.10.0) |
| 10 | SLES 11 SP3 (Kernel 3.0.13) |
| 11 | SLES 12 (Kernel 3.12.28) |

9.0 PRODUCT COMPLIANCE

9.1 Product Regulatory Compliance and Certifications

[Table 115] Certifications and Declarations

| Category | Certifications |
|----------|-------------------------|
| Safety | c-UL-us |
| | CE |
| | TUV-GS |
| | CB |
| EMC | CE (EU) |
| | BSMI (Taiwan) |
| | KC (South Korea) |
| | VCCI (Japan) |
| | Morocco (Morocco) |
| | RCM (Australia) |
| | FCC (USA) / IC (Canada) |

The three existing compliance marks (C-Tick, A-Tick, and RCM) are consolidated into a single compliance mark - the RCM.



Caution: Any changes or modifications in construction of this device which are not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment.

NOTE:

This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- Reorient or relocate the receiving antenna.
 - Increase the separation between the equipment and receiver.
 - Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
 - Consult the dealer or an experienced radio / TV technician for help.
- Modifications not expressly approved by the manufacturer could void the user's authority to operated the equipment under FCC rules.



Industry Canada ICES-003 Compliance Label:

CAN ICES-3 (B)/NMB-3(B)

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10.0 REFERENCES

[Table 116] Standards References

| Item | Website |
|---|---|
| PCI Express Base Specification Revision 3.0 | http://www.pcisig.com/specifications/pciexpress/base3/ |
| NVM Express Specification Rev. 1.2 | http://www.nvmexpress.org/ |
| Enterprise SSD Form Factor Version 1.0a | http://www.ssdformfactor.org/ |
| Solid-State Drive Requirements and Endurance Test Method (JESD218A) | http://www.jedec.org/standards-documents/docs/jesd218a |
| Solid-State Drive Requirements and Endurance Test Method (JESD219A) | http://www.jedec.org/standards-documents/docs/jesd219a |